

# **Photonics Modeling and Fabrication at Sandia National Laboratories**

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# Outline

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- **Sandia's background, mission, and capabilities**
- **Resonant Subwavelength Gratings**
- **Surface Plasmon Modeling**
- **Photonic Crystal Modeling**

# Sandia National Laboratories



California

New Mexico



- **Rich History: Part of Z-Division (LANL) in Manhattan Project; created as Nation's "Engineering Arm" in 1949 by President Truman**
- **Today 8,000 employees in New Mexico, California, Nevada, and Hawaii**
- **Responsible for research, development, engineering, and maintenance of U.S. nuclear weapons**
- **Responsible for all non-nuclear subsystems; the primary systems integration and engineering lab**
- **\$2B annual budget**
- **\$550M from other federal agencies**
- **\$50M from private industry through R&D partnerships**

***"Helping our nation secure a peaceful and free world through technology"***



# Sandia National Laboratories



**7000 full time employees**  
**~6000 in New Mexico**  
**~1000 in California**

**600 buildings, 5M square feet**

**1400 Ph.D.'s, 1700 Masters**  
**55% engineering**  
**33% science & mathematics**  
**12% computing**



# Sandia is Organized into 4 Strategic Management Units (SMUs) and 1 Initiative

## Military Technologies and Applications

Advanced Technology to Protect the Nation



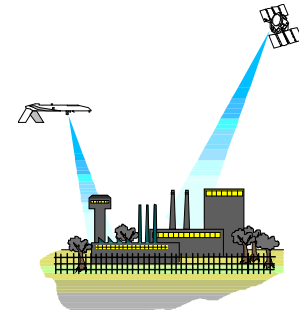
## Nuclear Weapons



Safe, Secure, Reliable Weapons



## Non-Proliferation & Assessments



Detection



Surveillance

## Energy & Infrastructure Assurance



Energy



Information



Transportation

## Homeland Security Initiative

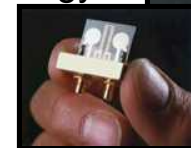


Architectural Surety

Anti-crime and anti-terrorism technology

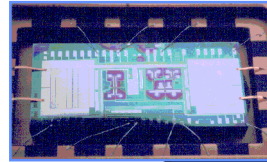


Smart Weapons



# Sandia's Enabling Capabilities Produce Miniature Sensors, Processors, and Communication Systems

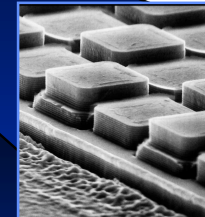
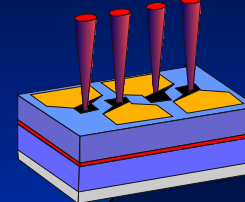
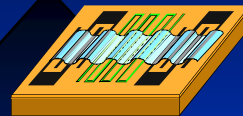
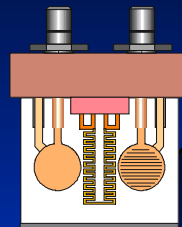
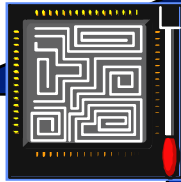
**Sense, Process, Communicate**



**Micromachines,  
Microelectronics**

**Microsensors**

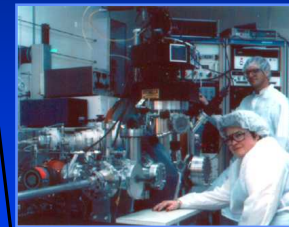
**Photonics,  
Microwave Circuits**



**Microelectronics  
Development Laboratory  
MDL**

**Integrated Materials  
Research Laboratory  
IMRL**

**Compound Semiconductor  
Research Laboratory  
CSRL**



**Over 30,000 ft<sup>2</sup> of  
clean room, Class 1  $\mu$ E  
Fabrication Facility**

**Materials Fabrication and  
Characterization, including Plasma  
Deposition and Surface and  
Interface State Characterization**

**MOCVD, MBE Deposition,  
Electron Beam Lithography,  
Reactive Ion Beam Etching**



# Our Mission Requires Unique and Distinguishing Facilities



**Integrated Materials  
Research Laboratory**



**Integrated Manufacturing  
Technologies Laboratory  
Complex (IMTL)**



**Microsystem and  
Engineering  
Science Applications  
(MESA) Facility**



**Compound  
Semiconductor  
Research Laboratory  
(CSRL)**



**Microelectronics  
Development  
Lab (MDL)**



**Processing and  
Environmental  
Technology Laboratory  
(PETL)**



**Science, and Engineering  
Laboratory (RMSEL)**

# Microsystems Science, Technology & Components

## Microelectronic Development Laboratory (MDL)

- Over 30,000 Square Feet of Clean Room Space
- State-of-the-art equipment for processing wafers up to 6 inches in Diameter
- 22 Separate laminar flow clean room bays- each with an independent air supply
- The Multiple clean room bays collectively provide over 12,000 square feet of class 1 clean room space.  
(Less than 1 particle 0.5 micron or larger per cubic foot of air.)

## Compound Semiconductor Research Laboratory (CSRL)

6500-square-foot (net) class 100 Clean Room Supports:

- Microsystem Skunkwork
- (Compound) Semiconductor Materials Growth and Processing
- RF & Photonic Device Technologies
- Microsensors Fabrication
- Hybrid Integration/Advanced Packaging



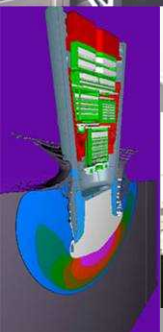


# Mesa Complex

# Components



## System Engineering



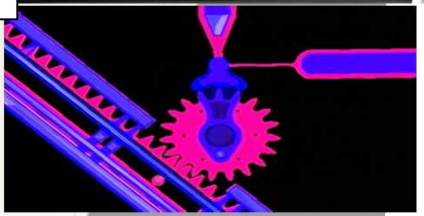
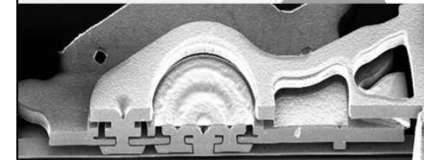
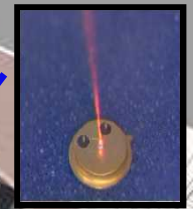
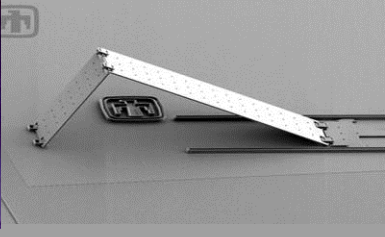
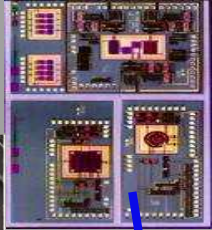
**MESA Provides Top Facilities and Equipment For Microsystems Design, Fabrication and Test Complete: FY06**

**Construction: \$77M  
Equipment: \$16M**

**TOTALS: Construction: \$246M, Equipment: \$168M  
Contingency: \$49M, TEC: \$463M**

**Construction: \$114M  
Equipment: \$139M**

## Science

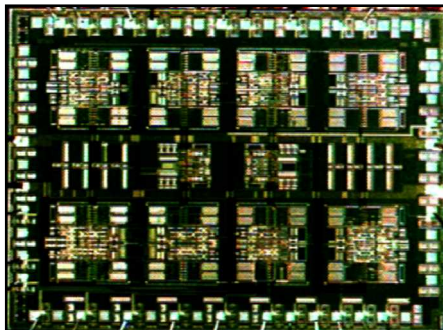


**Construction: \$55M  
Equipment: \$13M**



# Microelectronics Technologies

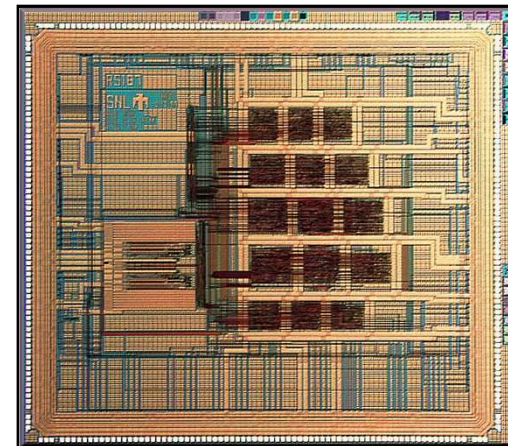
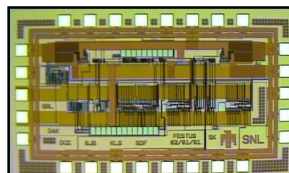
## Analog, Bipolar IC for 256-Channel Gamma Spectrometer



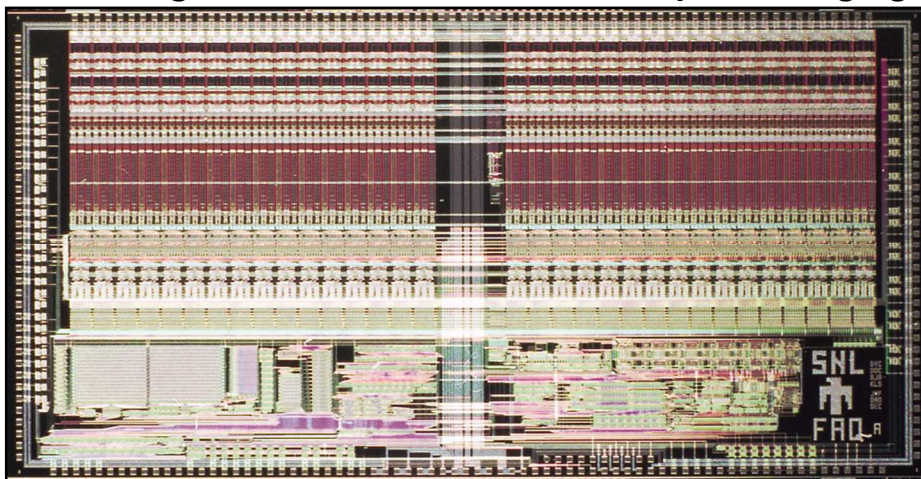
Charge Amp / Shaping Amp  
Peak Sample & Hold  
Anti-Pile up Lockout  
On-Chip Voltage References  
Draws less than 3 mA @ +7V

## Digital, Rad-Hard, CMOS Microcontroller

### Flyback Power Supply ASIC

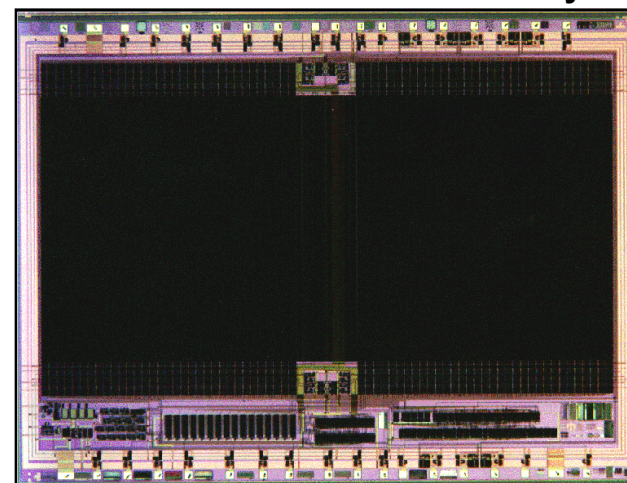


## Mixed Signal, Rad-Hard, CMOS IC for Optical Imaging



32 channel, low-noise, differential amplifiers & threshold circuits  
16-bit digital signal processor / 100 KHz, 10-bit A-to-D converter

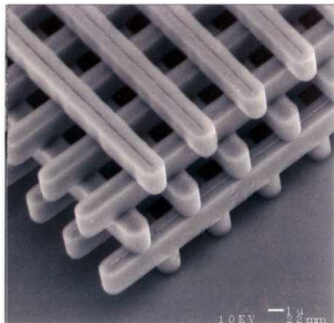
## Rad-Hard Non-Volatile Memory



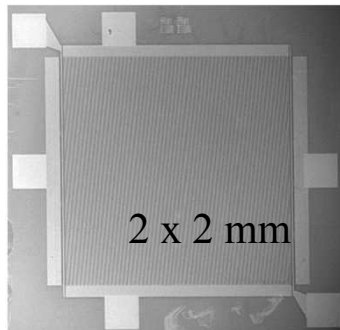
Transferred to Northrop-Grumman

# Sandia's Photonic Microsystems Technologies

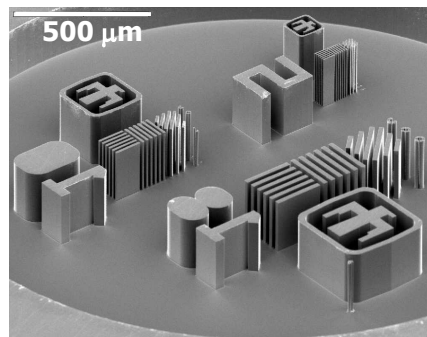
Photonic Crystals



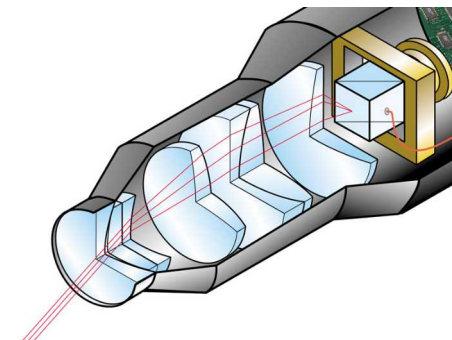
THz Detection &  
Quantum Cascade Lasers



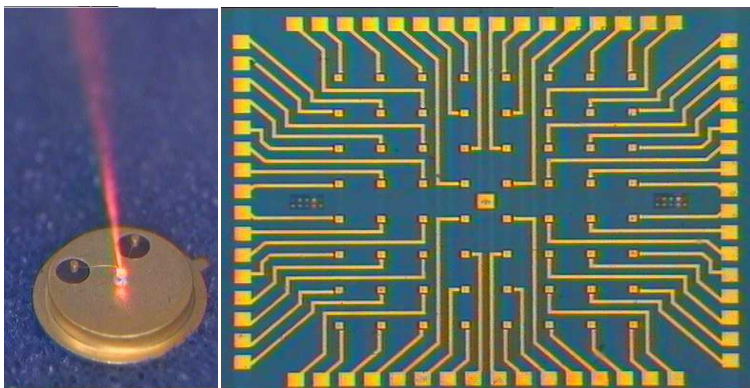
DXRL (LIGA)



Optical Design



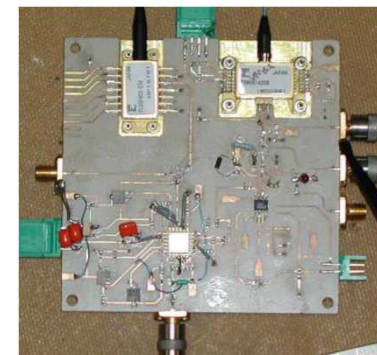
Visible & NIR VCSEL Arrays  
(Vertical-Cavity Surface-Emitting Lasers)



Subwavelength &  
Diffractive Optics



Novel Optical/Optoelectronic  
Package and Test



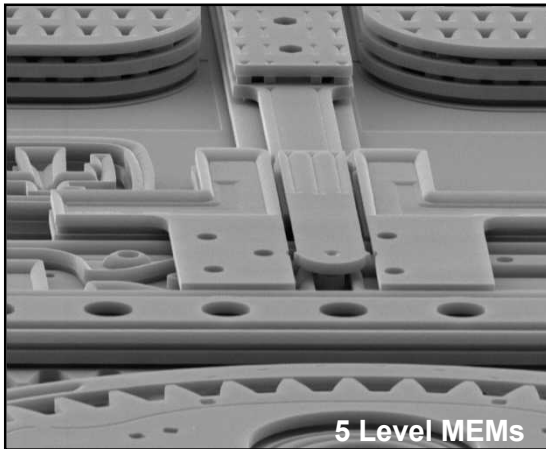
But, we are “technology agnostic” in our product developments



# Micro-Mechanics Technologies

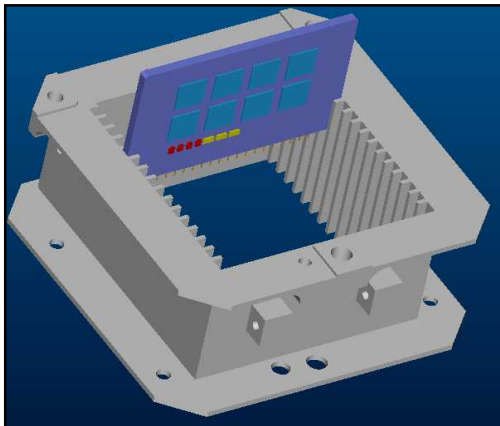
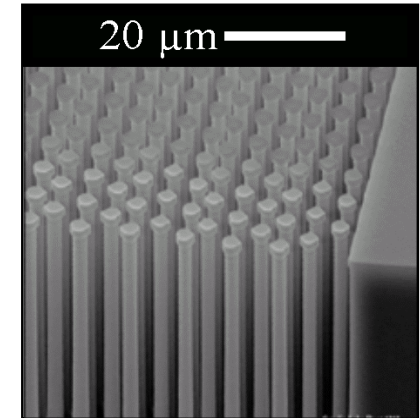
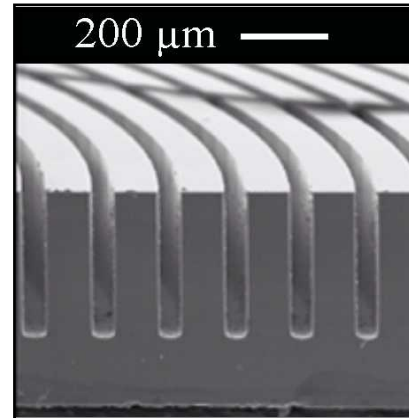
## Silicon Surface Micro-Machining

1 micron x 8 micron



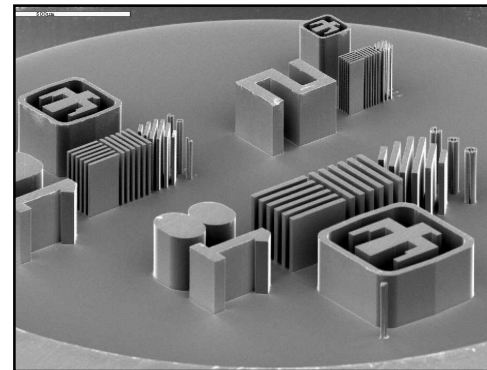
## High Aspect Ratio Si Deep Reactive Ion Etching

5 micron x 200 micron



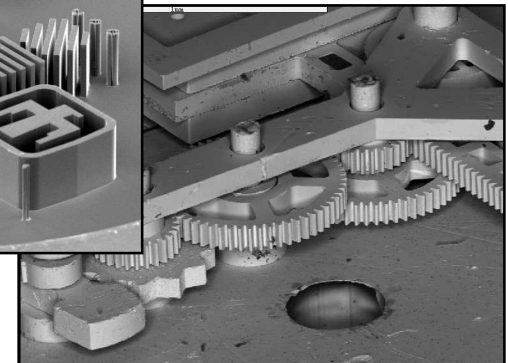
## Electro-Discharge Machining of Metals

2 mil tolerances

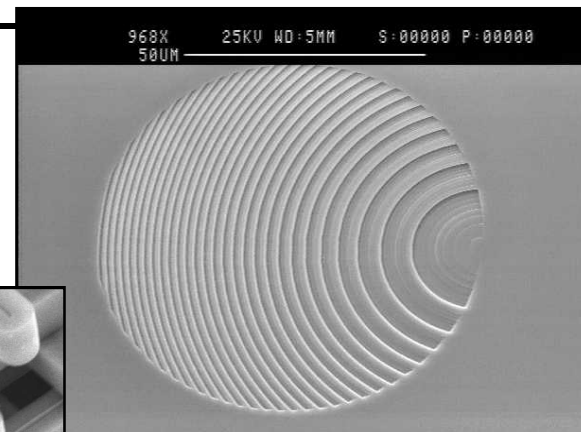
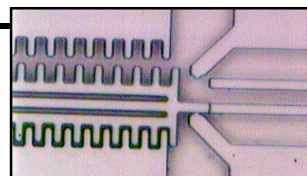
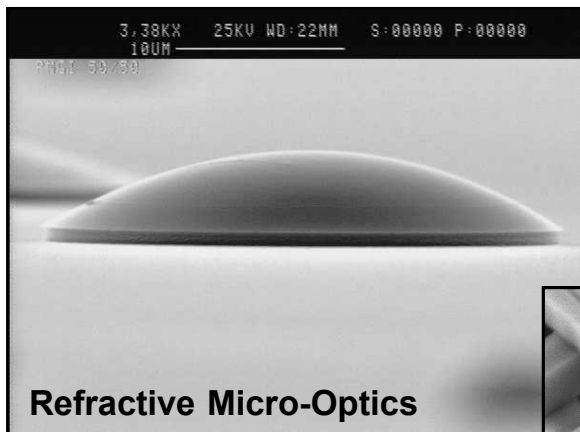


5 micron x 200 micron

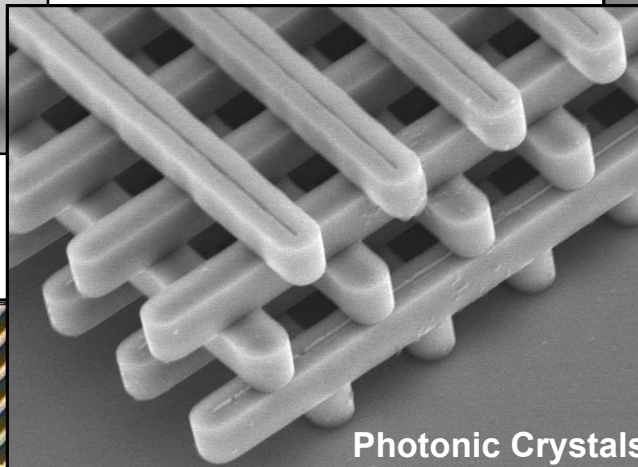
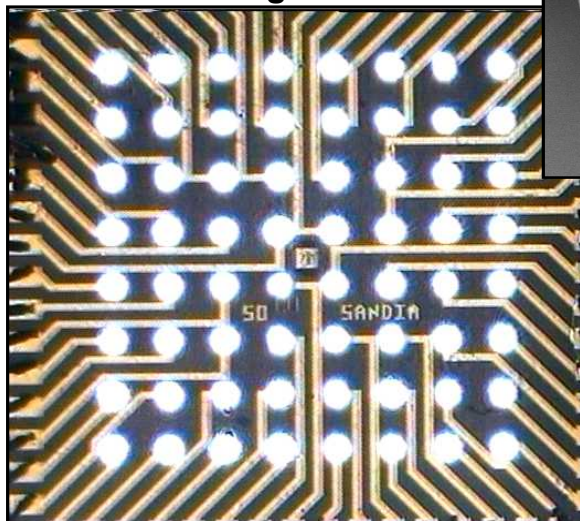
## LIGA Micro-Machining, Metals



# Micro-Optics Technologies

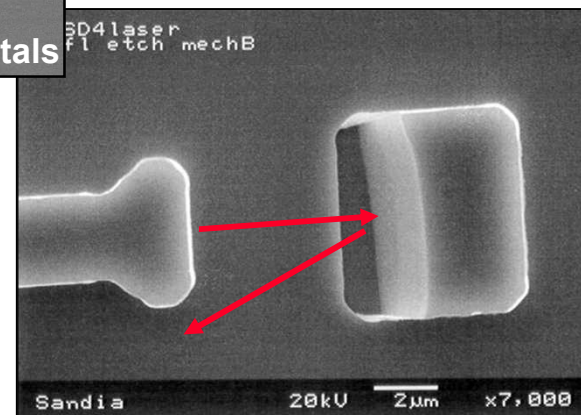


**Vertical Cavity Surface  
Emitting Lasers**

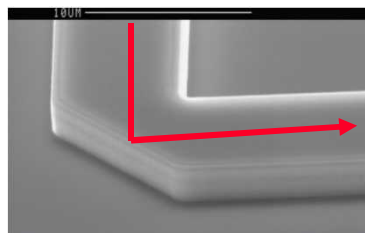


**Diffractive Micro-Optics**

**Curved, Offset, Tilted  
Micro-Mirrors & Lasers**



**Turning Mirrors**

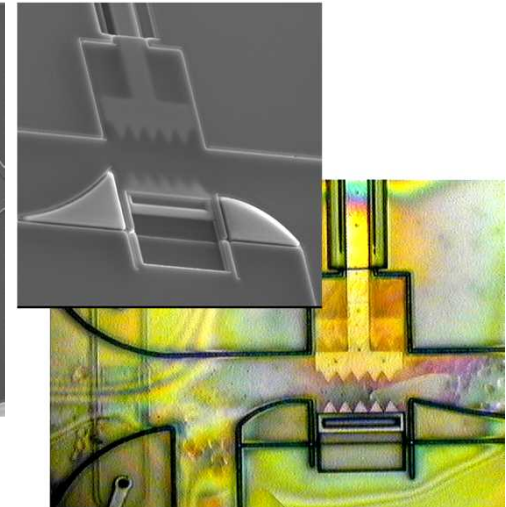
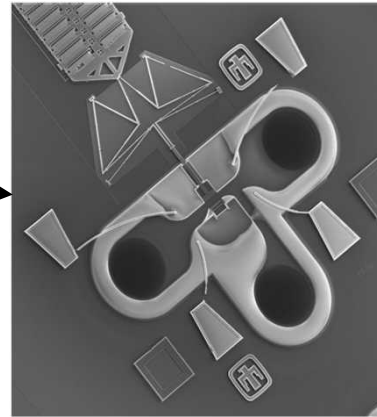
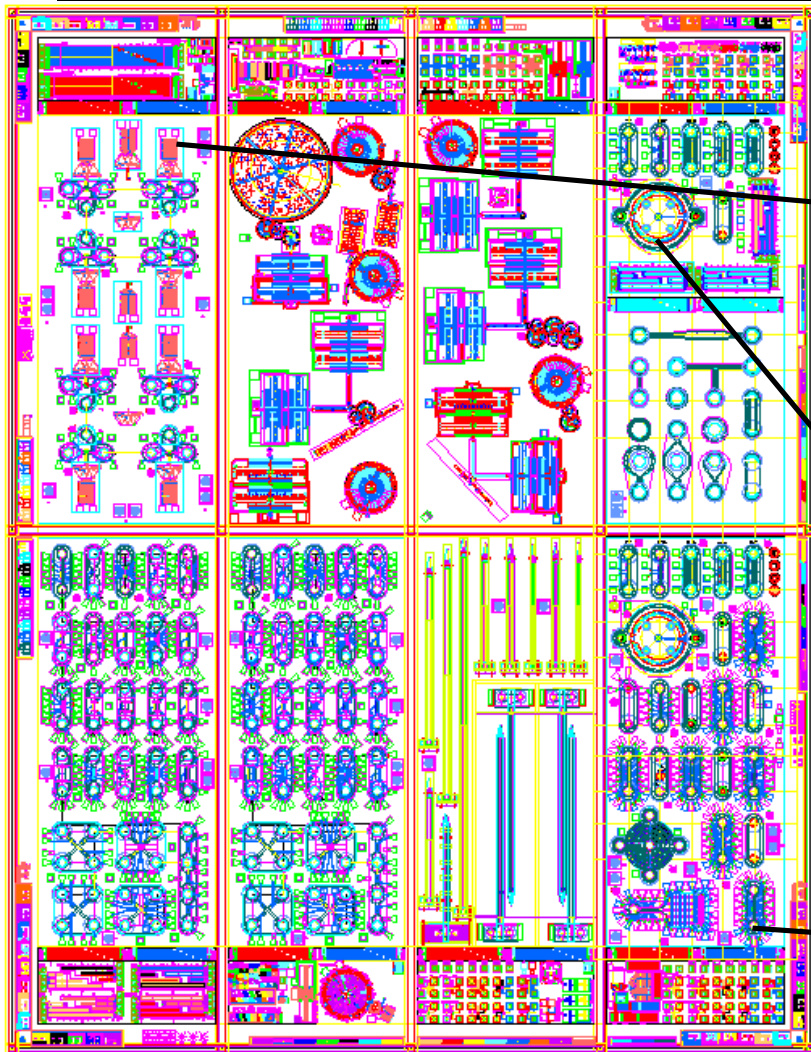


0.7 dB typ. excess loss

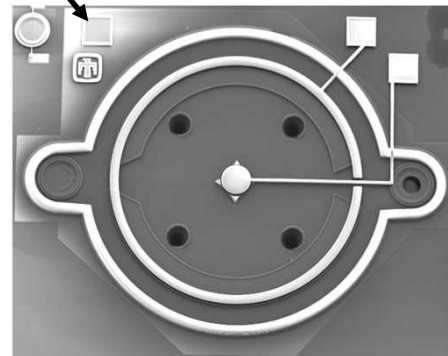
22.5° x 10° Output



# Surface Micromachined MicroFluidic Components

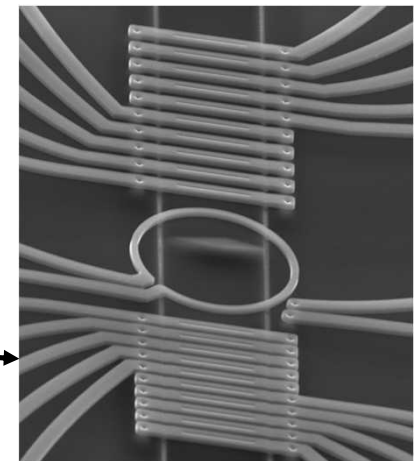


cellular manipulation



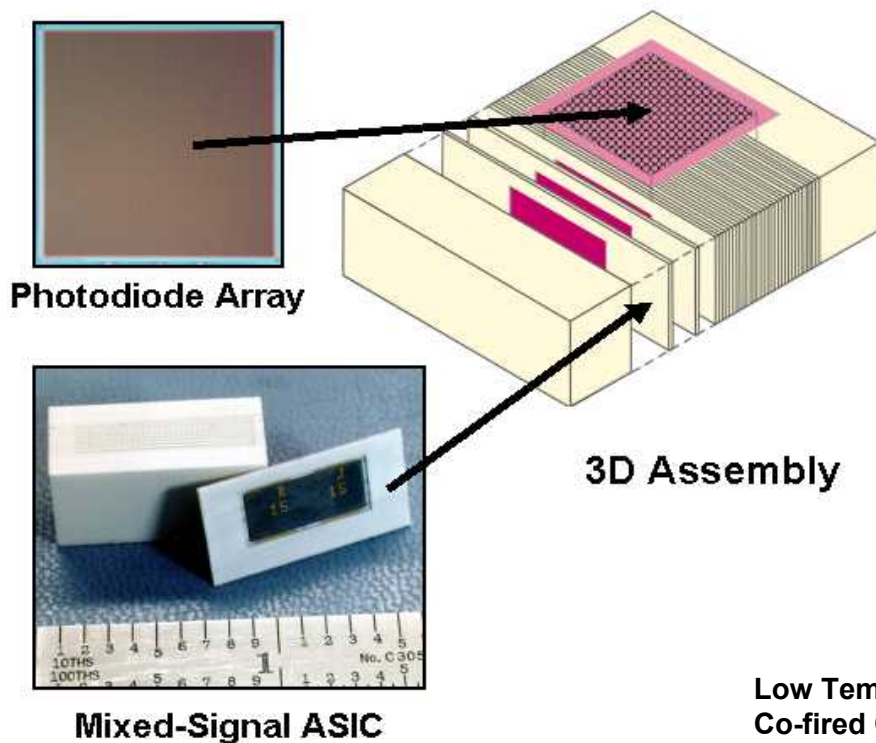
pumps

channels with  
electrodes

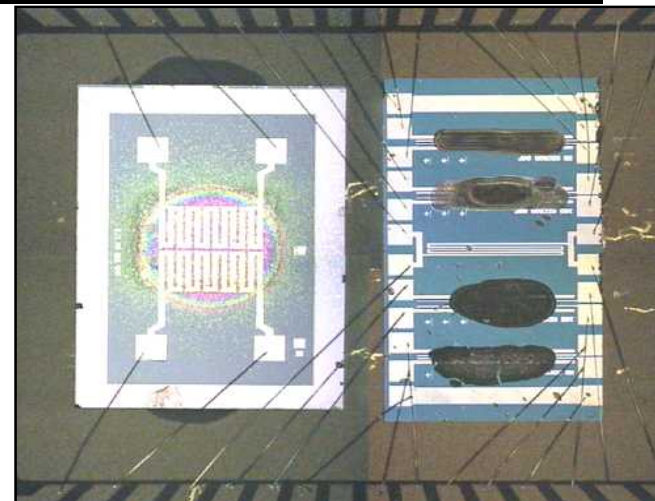


# Micro-Packaging Technologies

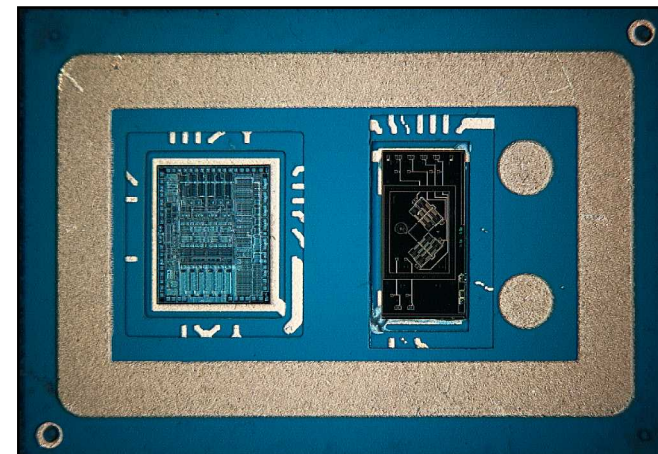
3-D Assembly reduces size by a factor of  $> 1000$



Low Temperature  
Co-fired Ceramic  
customized for  
Hi-Rel microsystems

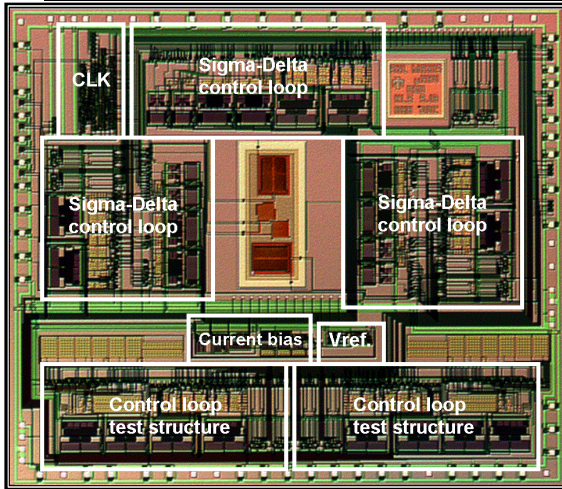


Preconcentrator / ChemiResistor array  
in Research Prototype package



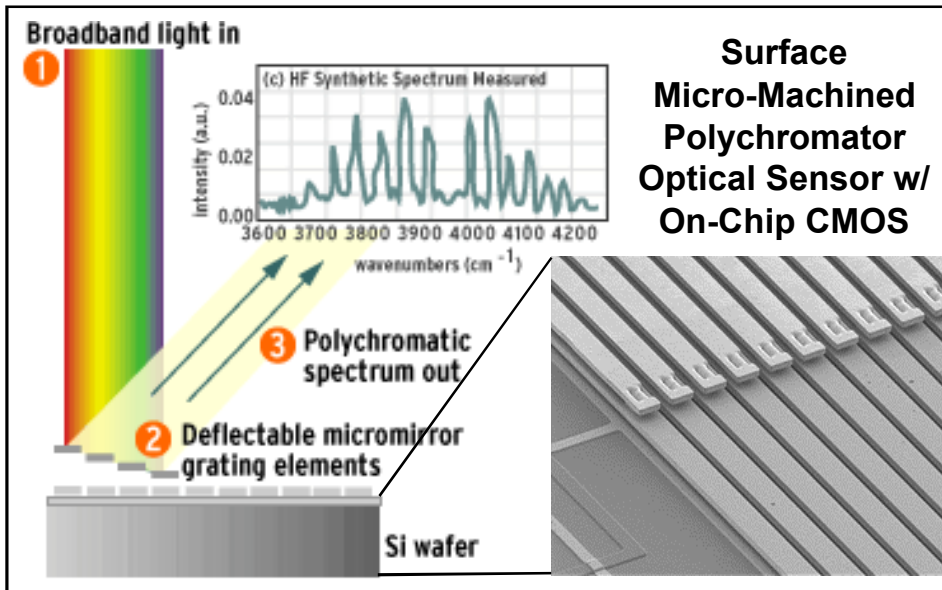
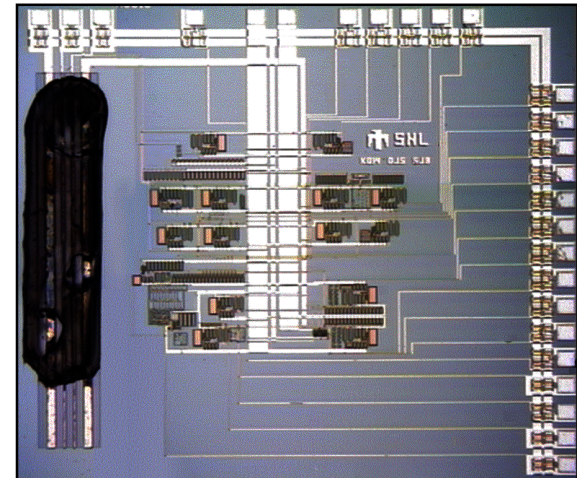


# Integrated Sensor Technologies

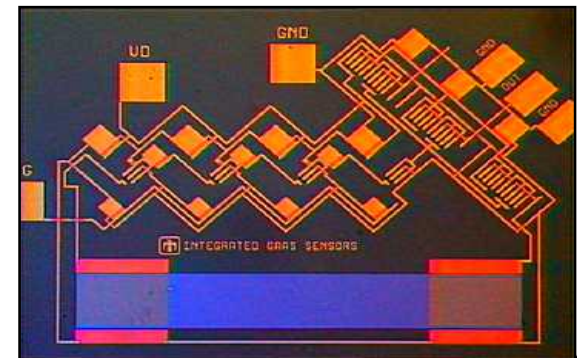


**3-Axis Surface  
Micro-Machined  
Accelerometer  
w/ On-Chip CMOS**

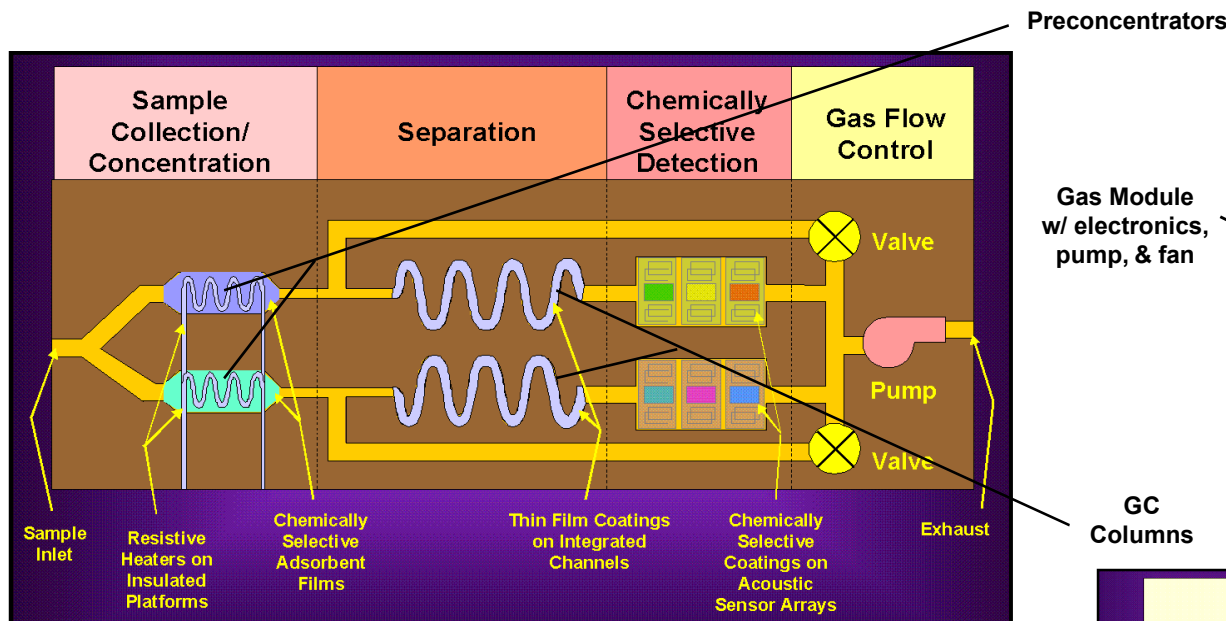
**Chemi-Resistor Gas Sensor  
w/ On-Chip Mixed-Signal CMOS**



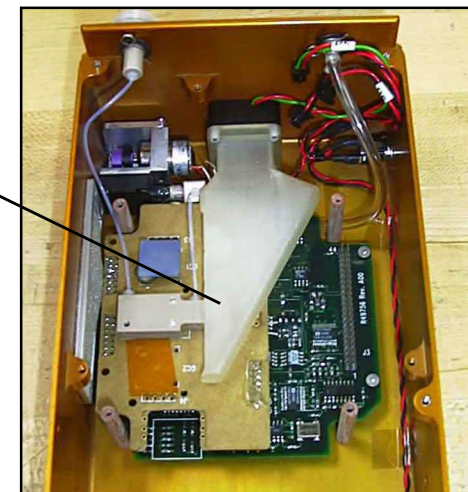
**Surface Acoustic Wave Sensor  
w/ On-Chip GaAs Electronics**



# MicroChemLab Gas Analysis Module



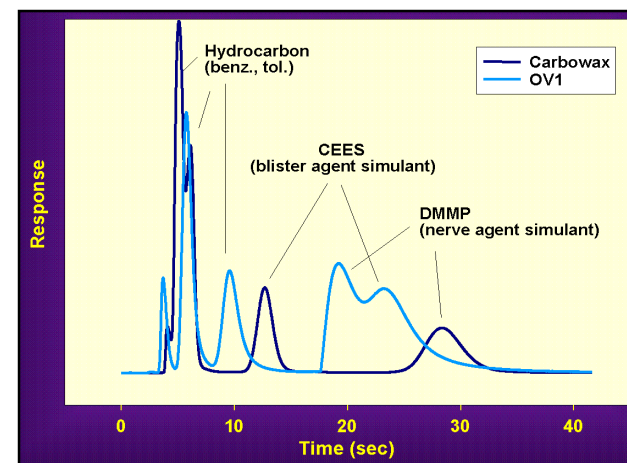
Gas Module w/ electronics, pump, & fan



GC Columns

## Gas Analysis Module Concept of Operation

- 1) Selective preconcentrators are loaded by moving large volumes of air through them using bypass valves.
- 2) Valves are closed and a thermal pulse is applied to the preconcentrators to release the concentrated sample.
- 3) Time separation of gases occurs in gas chromatograph column.
- 4) Coated surface acoustic wave (SAW) detectors respond to gases.
- 5) Pattern recognition algorithms operate on the SAW data and identify and quantify the gas concentrations.



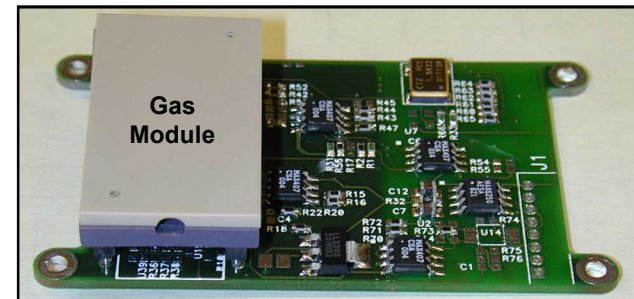


# Silver Fox Mini-UAV with SnifferSTAR Gas Analysis Unit

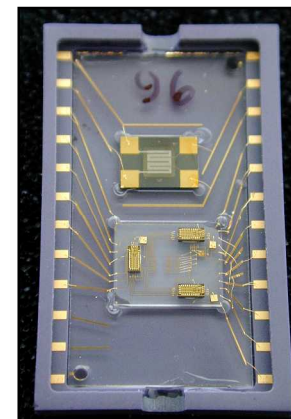


## SnifferSTAR Gas Analysis Unit

- Detects blister agents and nerve agents
- Weight less than 16 grams
- Runs on 500 mW, peaking to 125 mA, +5V
- Total analysis time is less than 20 seconds
- Lockheed-Martin & Sandia National Laboratories



← 2.5" →



**Gas Module  
Without Lid**

## Silver Fox Mini-UAV

- Deployed by battalion leaders
- Flies 500 to 1,000 feet high
- 20 lbs., 8 feet long, 6 foot wing span
- Detachable wings & tail fins, fits in a converted golf bag
- Launched from a compressed air catapult
- Runs on Glo-Fuel (model airplane fuel)
- Office of Naval Research & Advanced Ceramics Research



**Award Winner for 2003**

M. R. Daily, 1738  
(505) 844-3145  
dailymr@sandia.gov

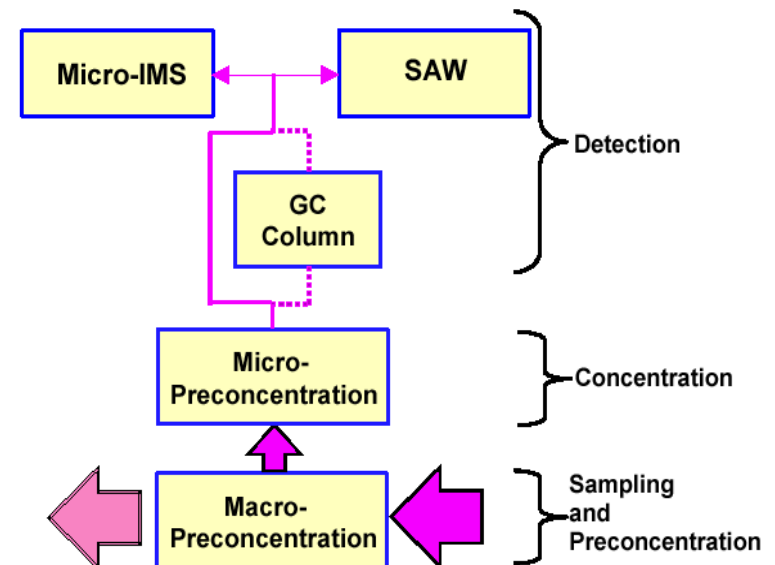
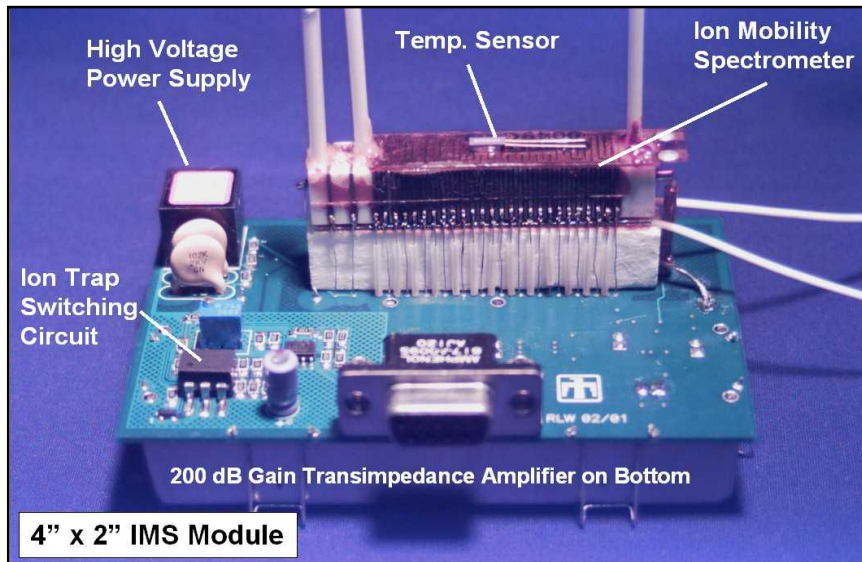
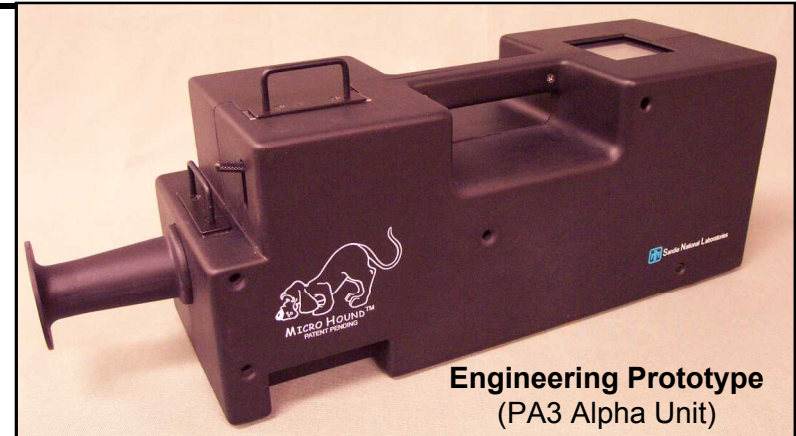




# MicroHound Explosives Detection System

## MicroHound Explosives Detection Handheld Units

Ten MicroHound handheld explosive detection units have completed acceptance testing and have been delivered to the government customer. The MicroHound combines Center 4100's explosive sample collection and preconcentration technology with an Ion Mobility Spectrometer microsystem developed in Center 1700. The MicroHound is 1/4 the cost, 1/3 the weight (12 lbs), 1/2 the size, and has 4 times more single-charge operating life compared to competing products in the same performance class. It can detect trace amounts (nanograms) of explosives on equipment and people.





# Low-sideband resonant subwavelength grating array design

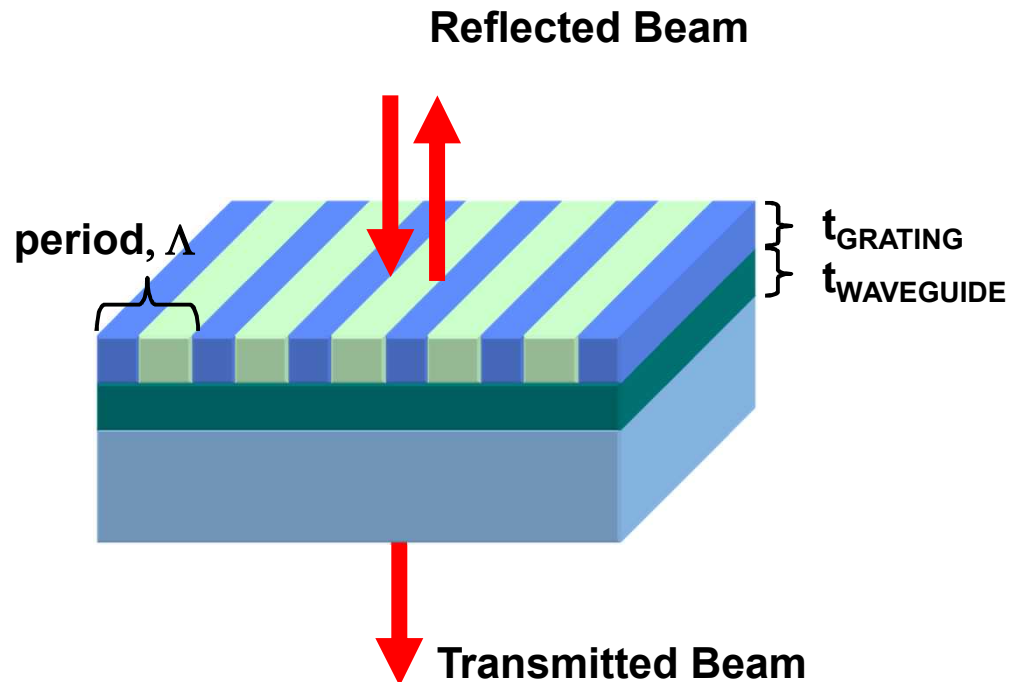
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J. R. Wendt, T. R. Carter, and S. Samora

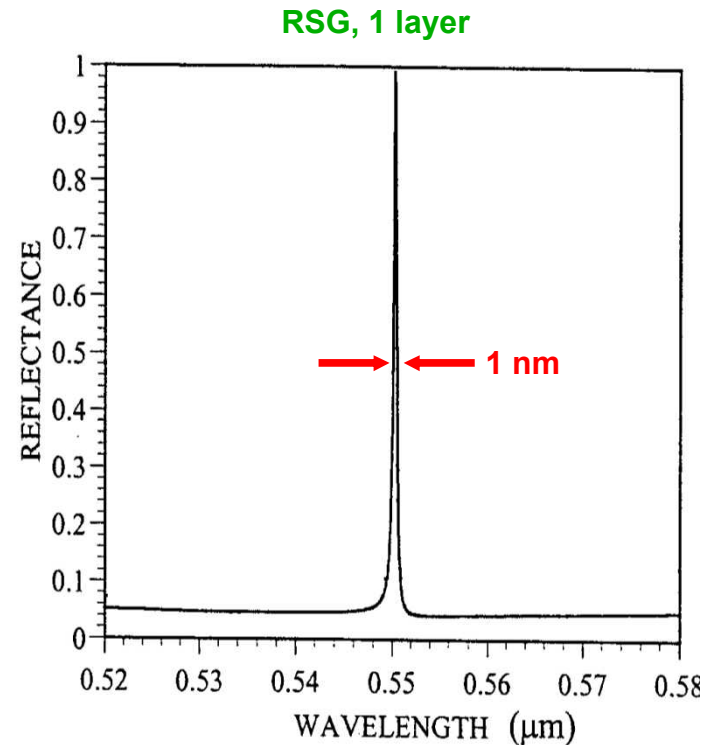
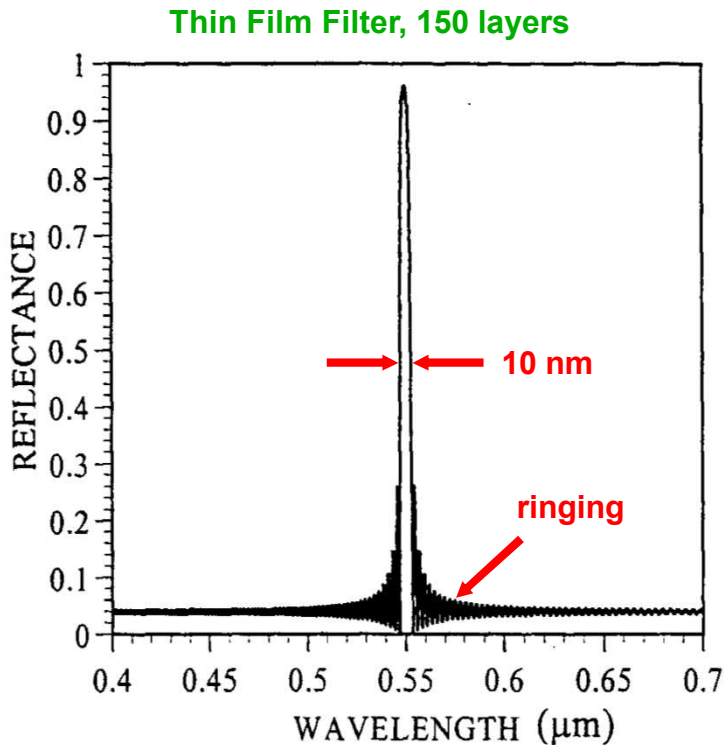
- Also called guided-mode resonant filters in the literature.
- Offers narrow wavelength band, narrow angular band reflector with low sidebands.
- Easier to pixelate than thin film filters.

# Resonant Subwavelength Grating

- Light incident from above see a grating coupler and a waveguide.
- Light at specific angles, polarizations, and wavelengths can couple into the waveguide mode.
- The grating then couples this energy back out the top surface, leading to a reflected beam.



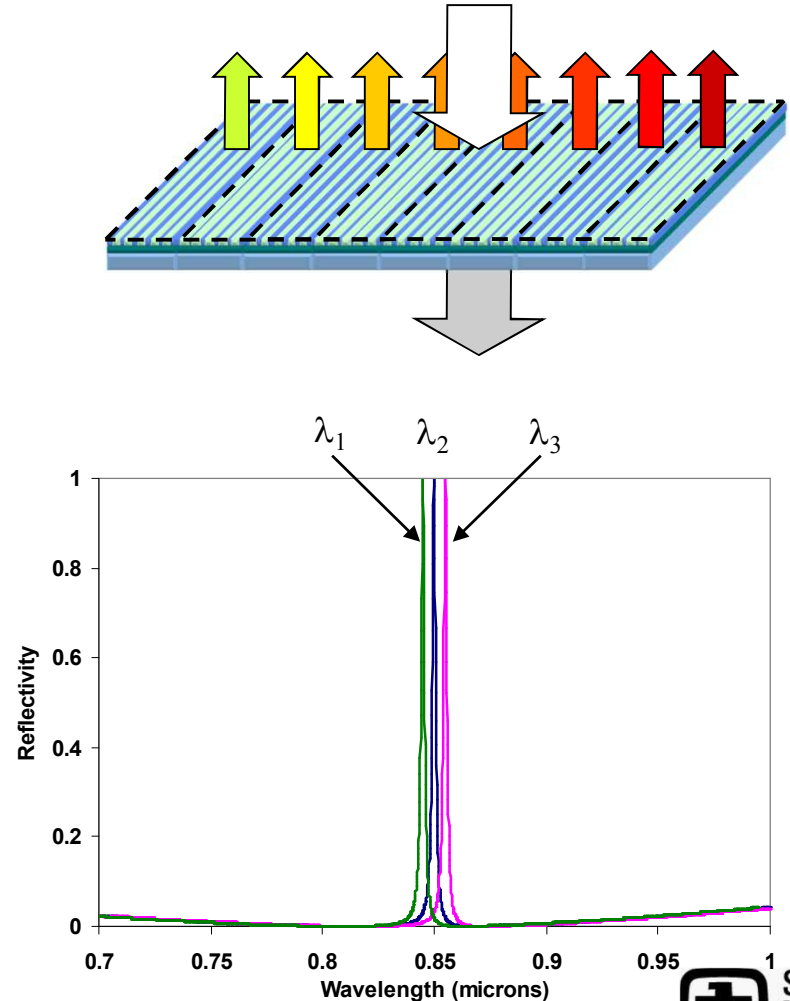
# Comparison of Thin Film Filter to RSG



- Narrow wavelength band (0.01nm to 20nm) reflected 100%
- Reflected light in narrow angular band ( $\sim 1\text{mrad}$ ) for security applications
- Superior high efficiency and smooth sidebands, compared to thin film technology

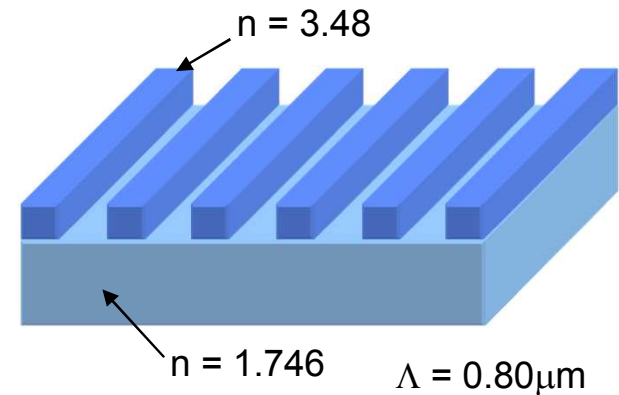
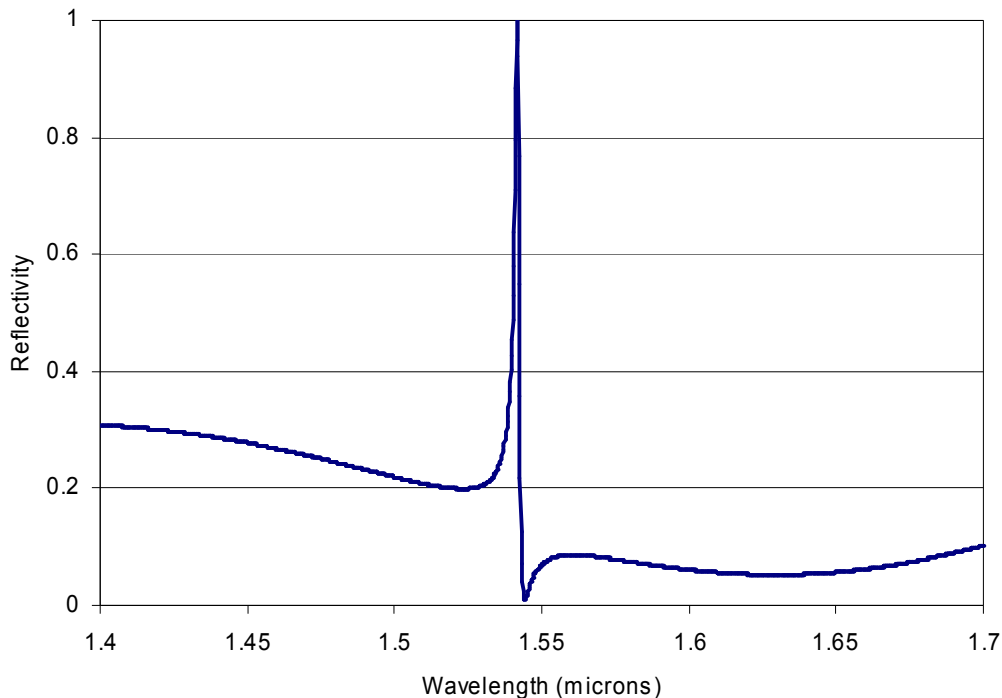
# Arrayed Subwavelength Resonant Gratings

- Easily implemented as pixilated, spectrally encoded array to match to detector array or chem/bio sensor array.
- FWHM of 1-2nm.
- Low sideband over wide range (0.7 to 1.0 $\mu\text{m}$ ) for every pixel.





# Typical Resonant Subwavelength Grating Reflectivity



**Narrow resonant peak, but considerable sideband reflectivity**

**Unacceptable for an array**

# Variables in RSG Design

2-layer design allows AR-coat design for low sidebands.

## Global variables

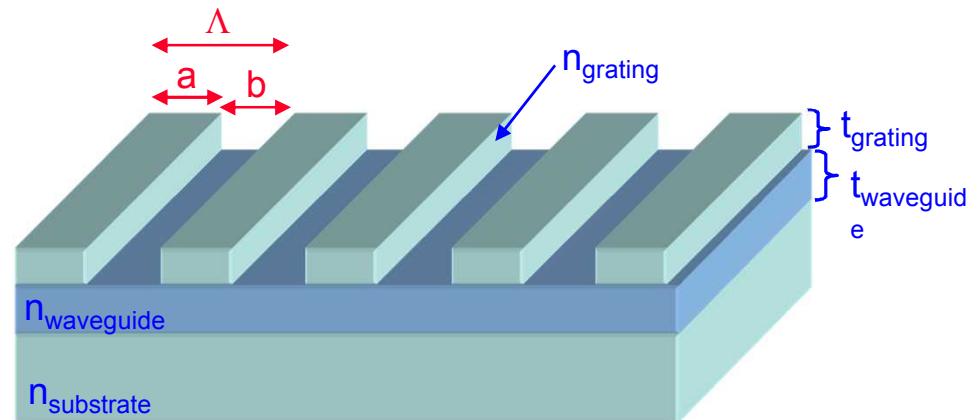
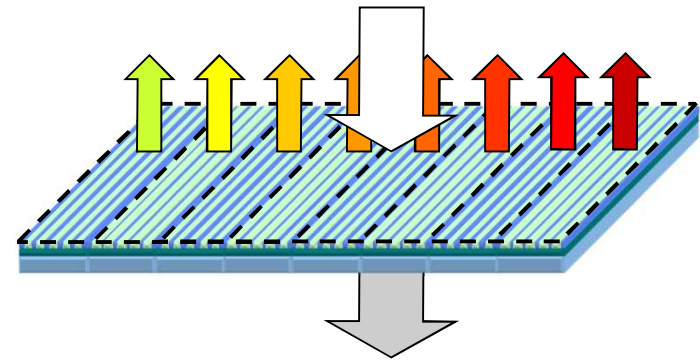
Indices of refraction

Layer thicknesses

## Pixel variables

Grating period

Grating duty cycle  
 $dc = a/(a+b)$





# Material Choices

---

- **Fused silica substrate**

Robust material for visible and near-IR applications

- **TiO<sub>2</sub> waveguide layer**

Offers high index of refraction

Grown in-house or purchased from vendor

- **SiO<sub>2</sub> grating layer**

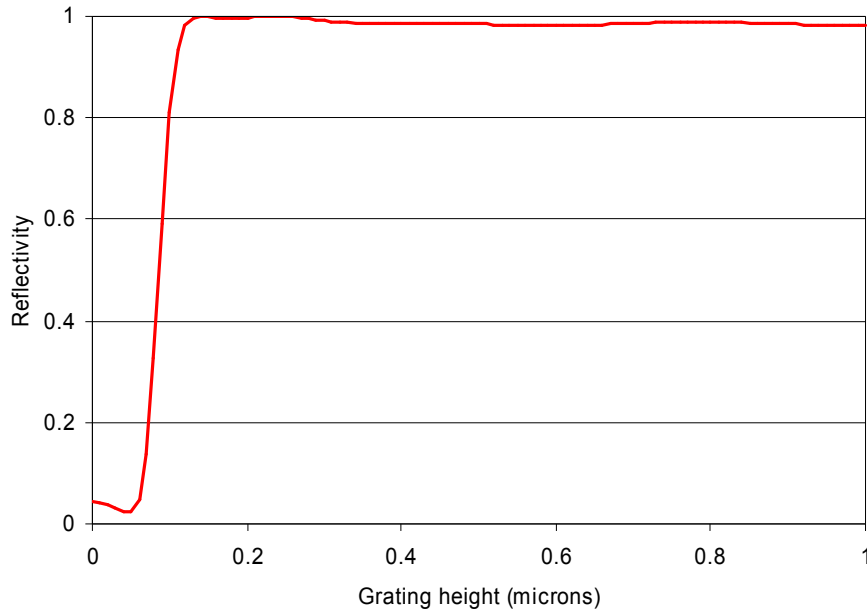
Relatively easy to deposit and etch

Mature in-house process

- **Chosen materials allow for effective AR coating**

# Grating thickness determination

On-resonance reflectivity as a function of grating height



$$\lambda_o = 850\text{nm}$$

$$n_{\text{grating}} = 1.4525$$

$$t_{\text{waveguide}} = 185\text{nm}$$

$$n_{\text{waveguide}} = 2.15$$

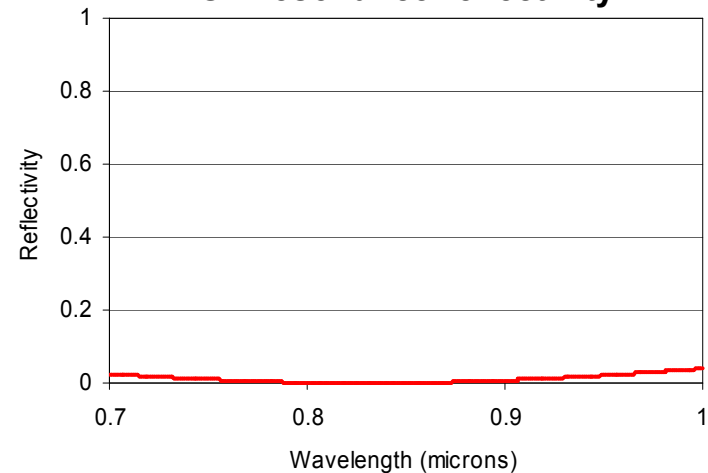
$$dc = 0.4$$

$$n_{\text{substrate}} = 1.4525$$

Resonance condition is relative insensitive to the grating height after  $0.12\mu\text{m}$ .

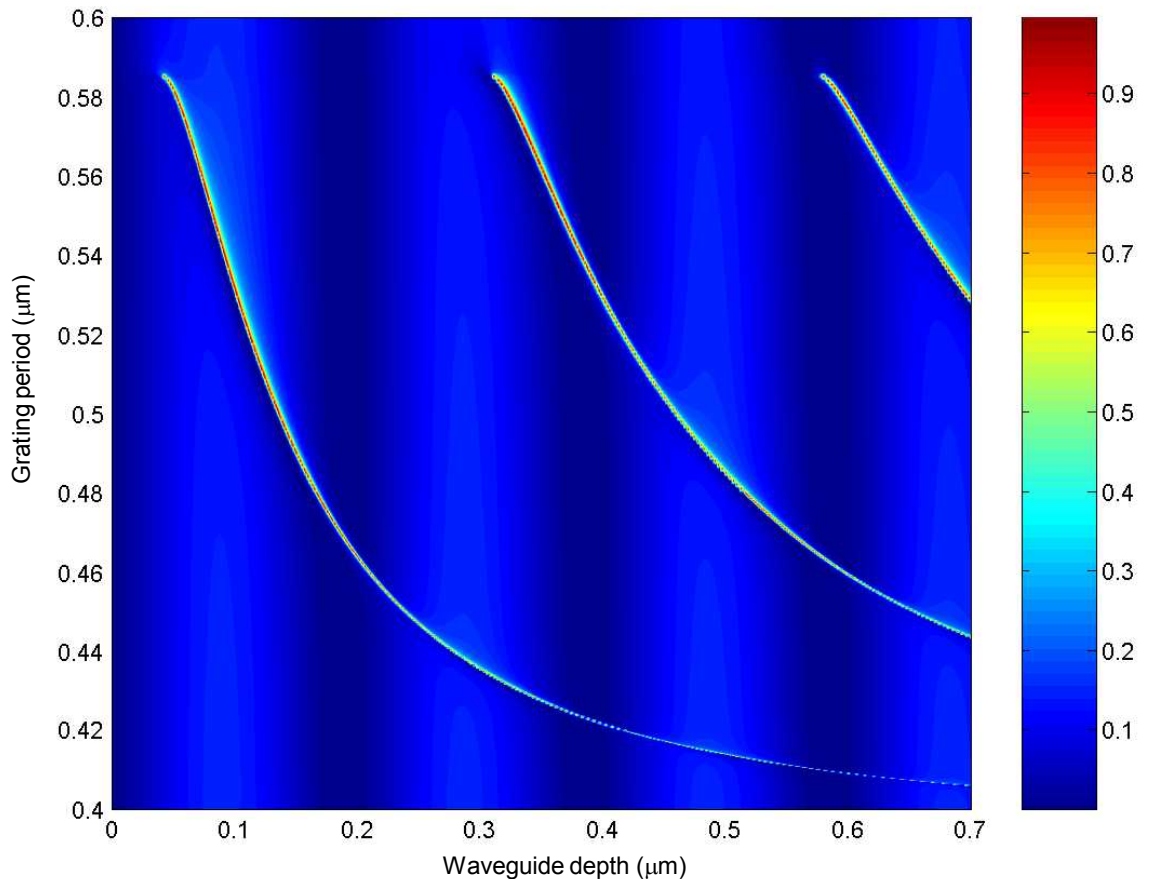
This allows us to use the grating height as a parameter in lowering sideband reflectivity.

Off-resonance reflectivity



- Replace the grating layer with a uniform layer with an equivalent effective index
- Optimize the thickness to minimize the reflectance near the center of the band

# Reflectivity of infinite grating illustrating antireflection effect and resonant condition



$$\lambda_o = 850\text{nm}$$

$$t_{\text{grating}} = 0.14\mu\text{m}$$

$$dc = 0.4$$

$$n_{\text{grating}} = 1.4525$$

$$n_{\text{waveguide}} = 2.15$$

$$n_{\text{substrate}} = 1.4525$$

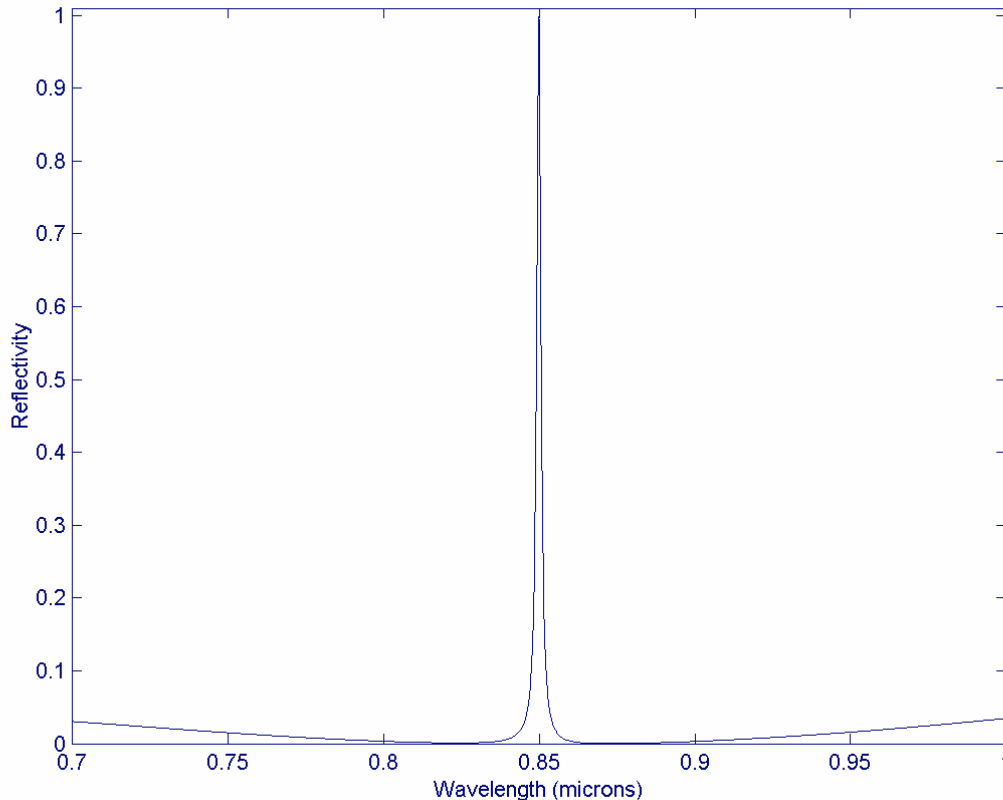
TE, normal incidence

**Design around a point where the resonant condition coincides with a low background reflection**



# Reflectivity for an array pixel centered at 850nm

---

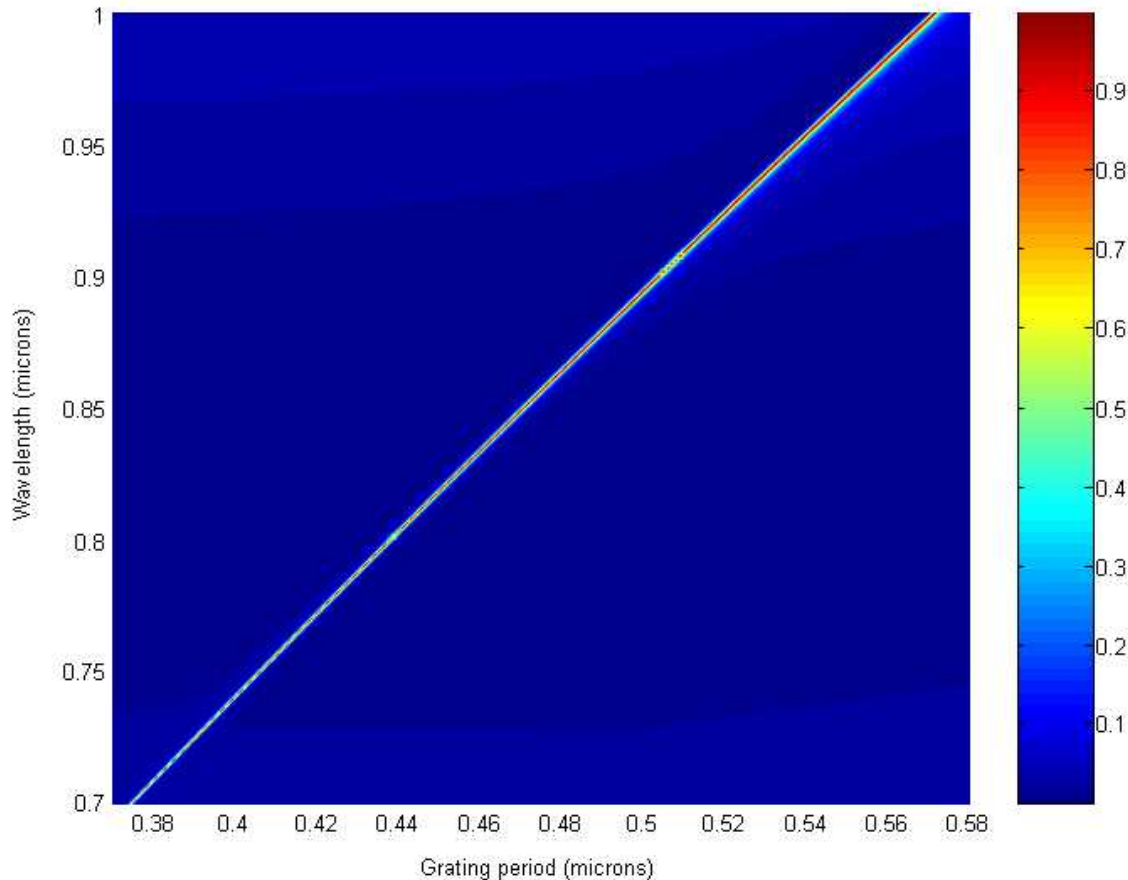


**FWHM of 1.6nm.**

**Reflectivity in sidebands  
under 0.04.**

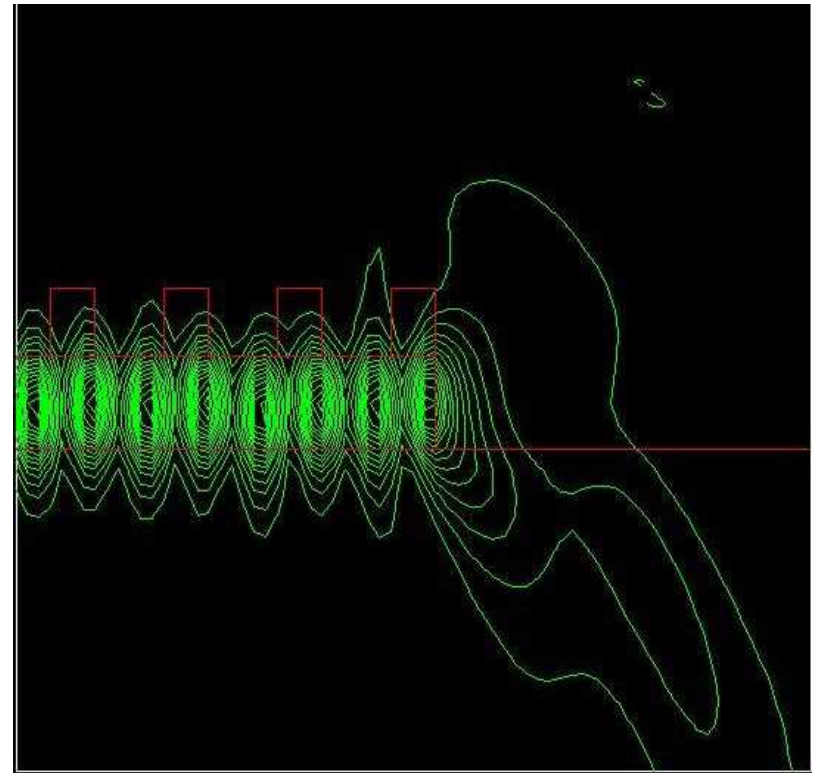
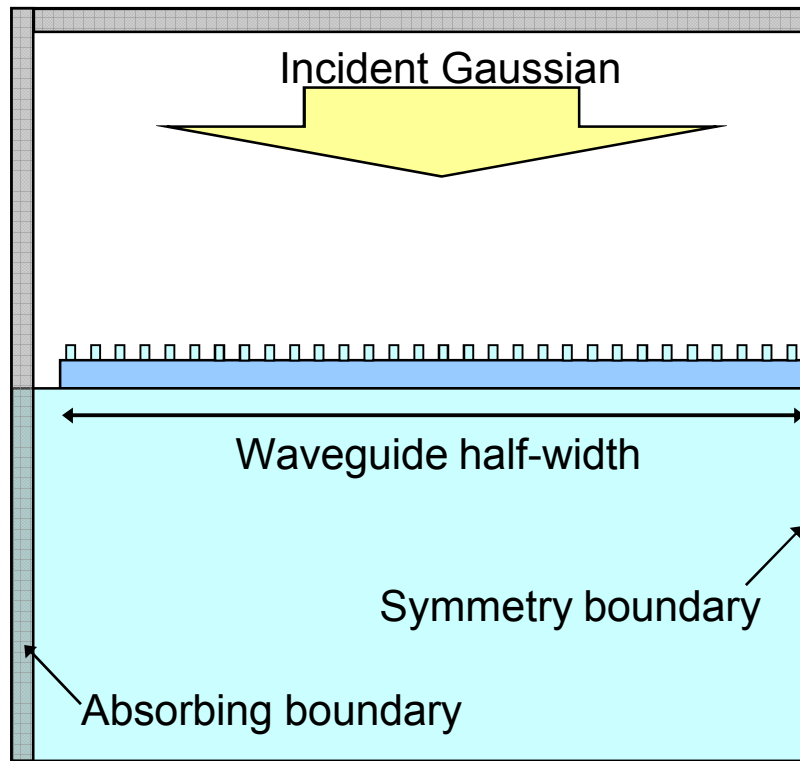
**Peak centered in  
minimum of background  
reflectivity.**

# Tunability of resonant condition with grating period



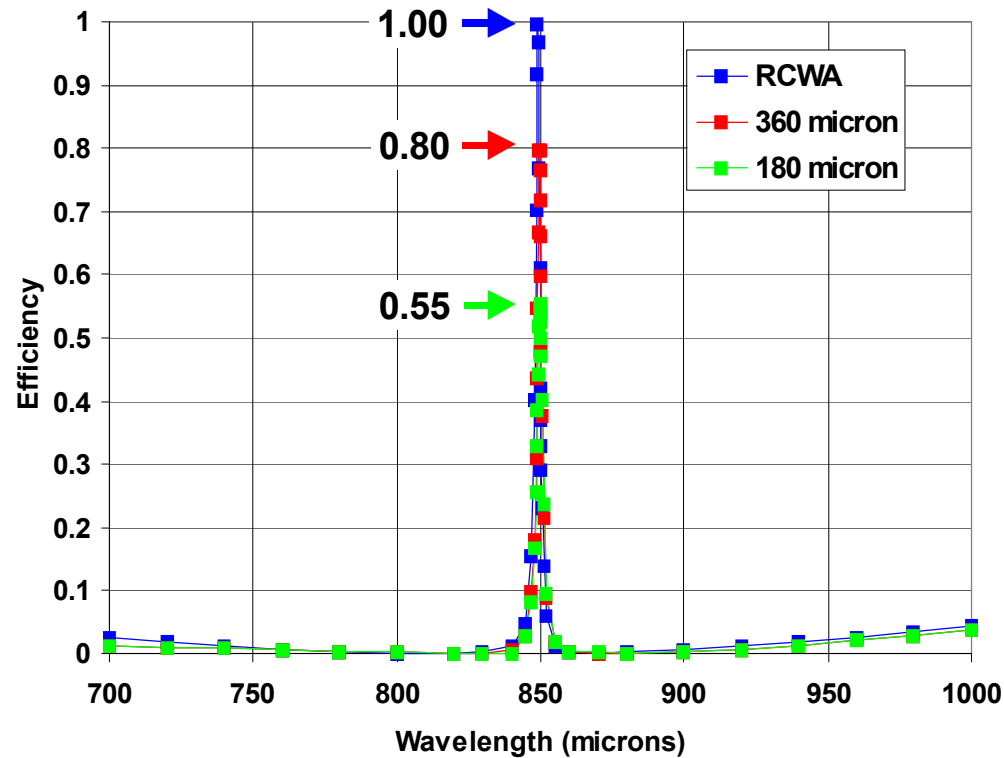
**Linear variation of  
resonant wavelength  
with grating period  
while maintaining low  
sideband reflectivity**

# Modeling of finite extent gratings using Helmholtz finite difference method



**Reflection back into structure from end facet may enhance or degrade reflectivity depending on position of facet.**

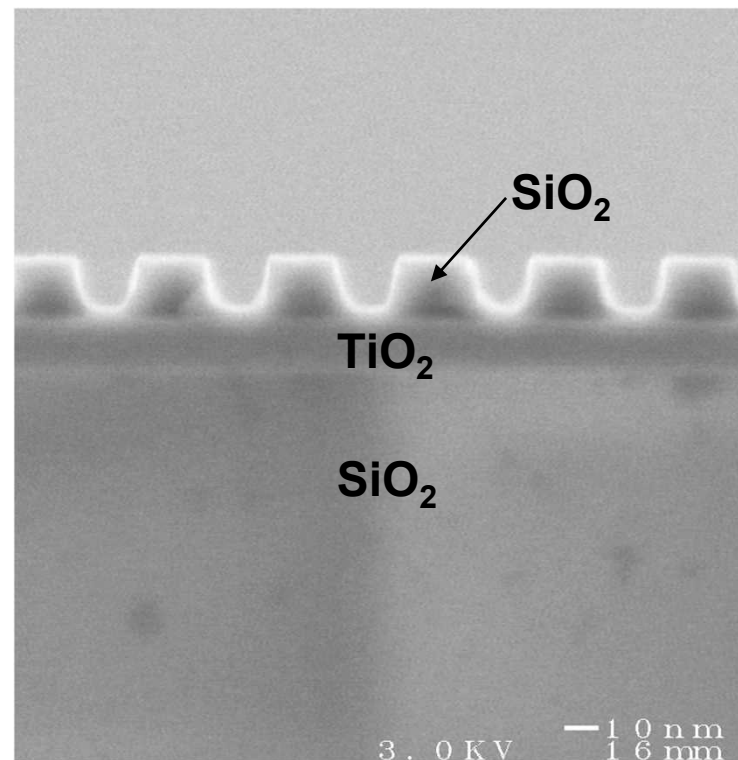
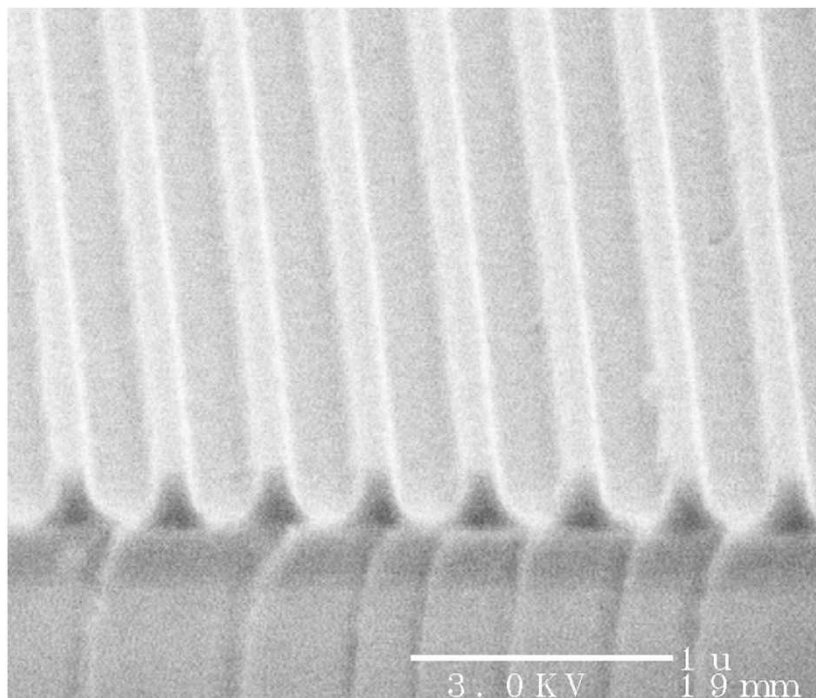
# Effect of finite grating size



- Sideband reflectivity remains low
- FWHM only increases to 2.3nm for 180 $\mu$ m wide pixel

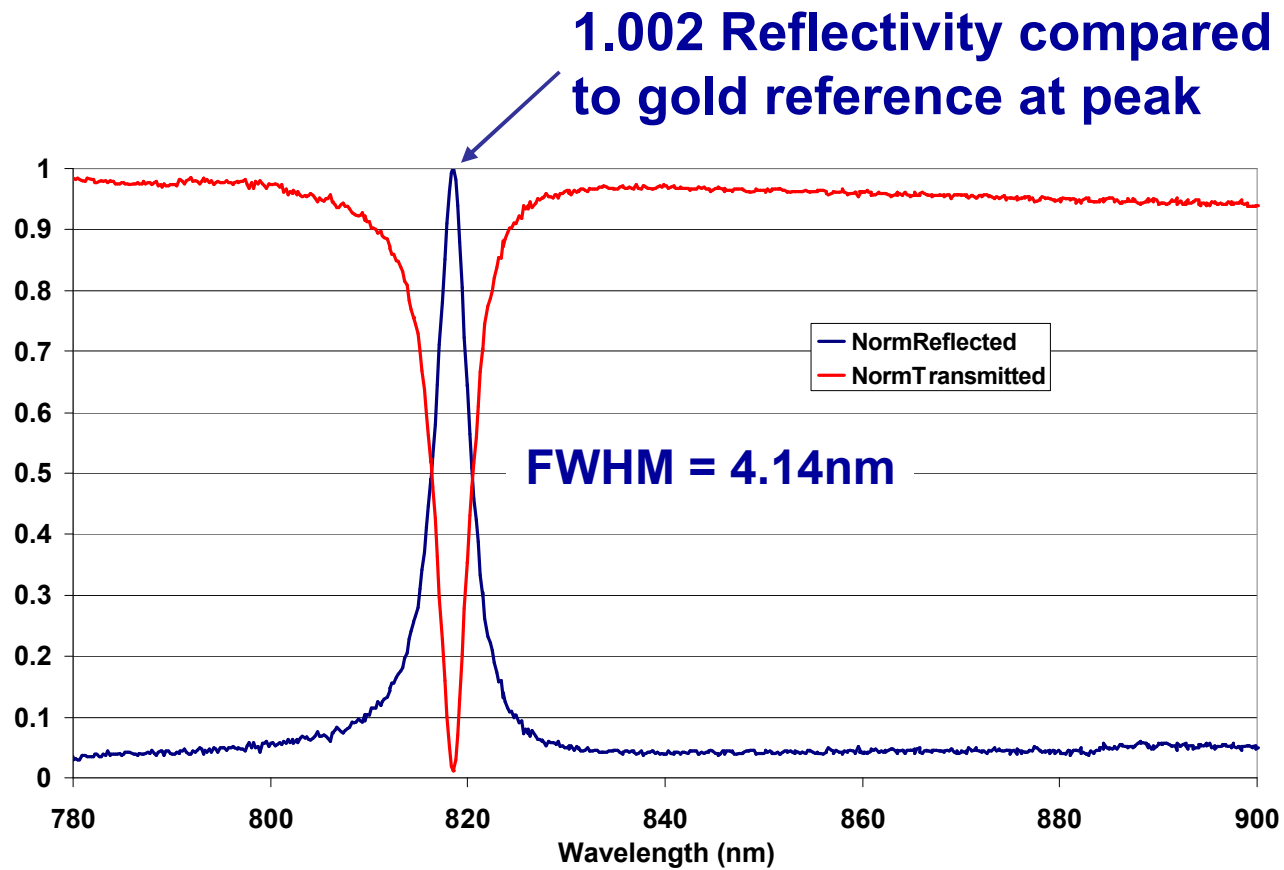


# RSG SEMs

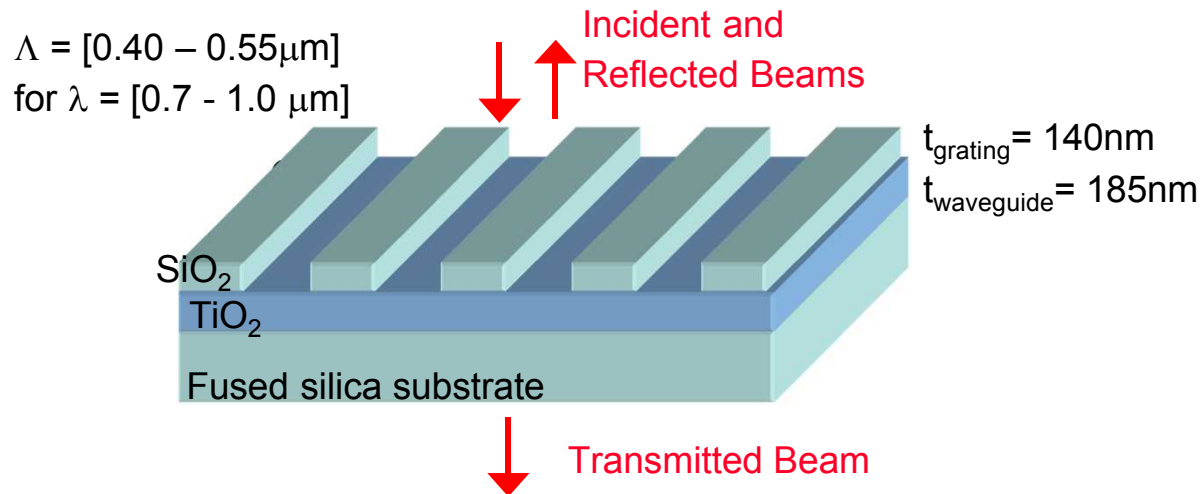




# Measured Response



# Summary



- Grating pitch linearly varies filter wavelength response
- Material and parameter configuration allows effective AR coat design for low sidebands across wide wavelength range
- Realistic modeling of finite-extent devices



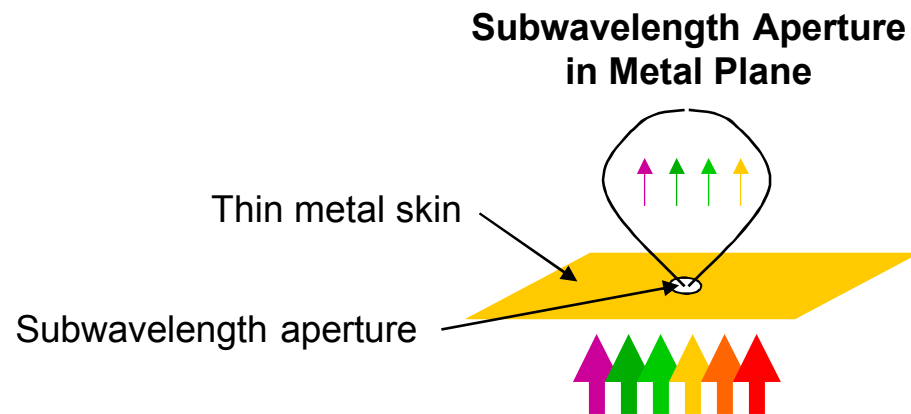
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# **Surface Plasmon-Assisted Transmission and Emission from Subwavelength Patterned Apertures**

**David Peters, I. El-Kady, S. A. Kemme, and G. R. Hadley**

# Interesting surface wave effects in patterned apertures

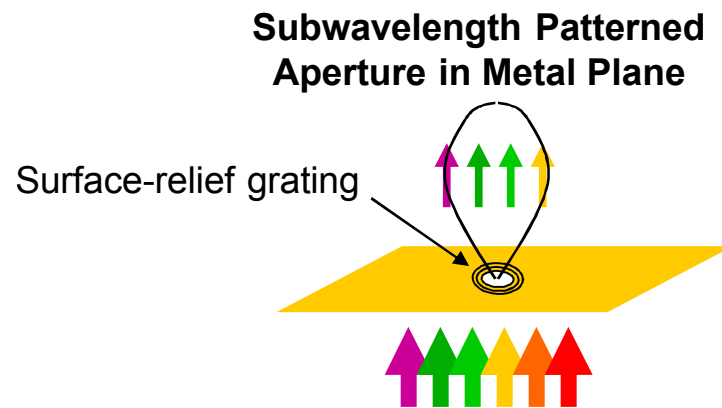
A small aperture in a metal surface allows very little light through.



Patterning a surface-relief grating around the aperture allows much more light of certain wavelengths through the aperture.

Large enhancement factors reported.

Leads to an exit beam that beats the diffraction limit.



Applications in sensors, near-field microscopy,  
photolithography and data storage.

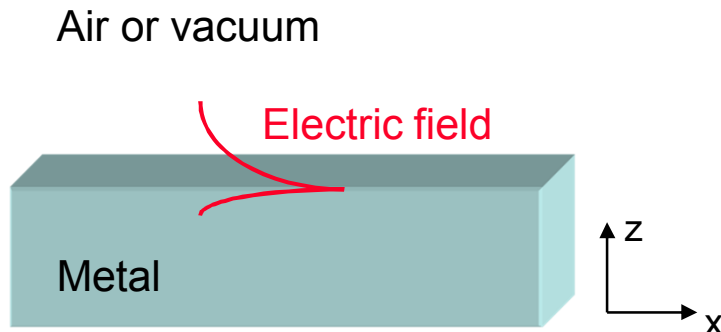


# Surface Waves

Surface plasmons are electromagnetic fields that exist only at metal/dielectric interfaces.

It is impossible to directly couple to a surface plasmon with an incident photon at a uniform metal surface interface.

Highly dependent on surface properties.



$$E = E_o \exp[i(k_x x + k_z z - \omega t)]$$

$k_x$  is real, therefore propagates.

$k_z$  is imaginary, therefore decays exponentially.

*Examples of skin depth:*

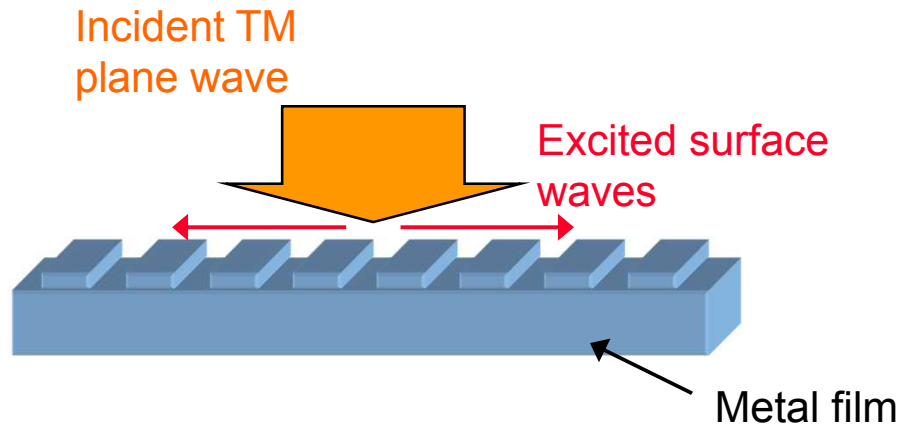
*At air/gold interface at  $1\mu\text{m}$ :*

$$\delta_{air} = 1\mu\text{m} \quad \delta_{Au} = 23\text{nm}$$

*At air/silver interface at  $500\text{nm}$ :*

$$\delta_{air} = 277\text{nm} \quad \delta_{Au} = 21\text{nm}$$

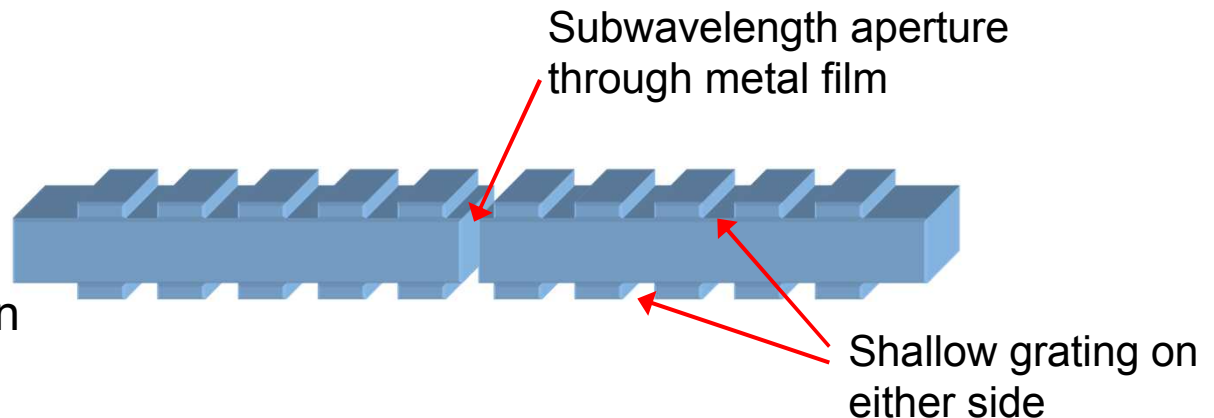
# Photon-Surface Plasmon coupling



A metal grating matches the momentum of the incident wave to the evanescent surface waves, allowing coupling of energy.

Surface waves may travel along an aperture in a metal film.

A second grating may then couple to a propagating wave.





# Modeling

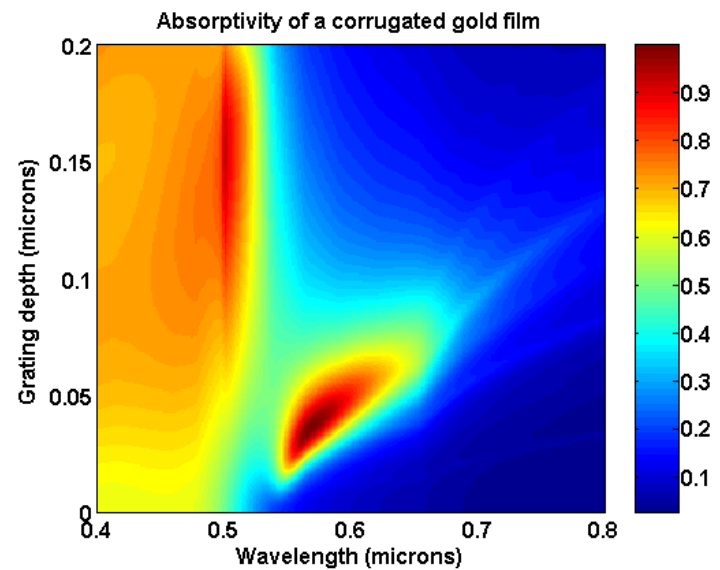
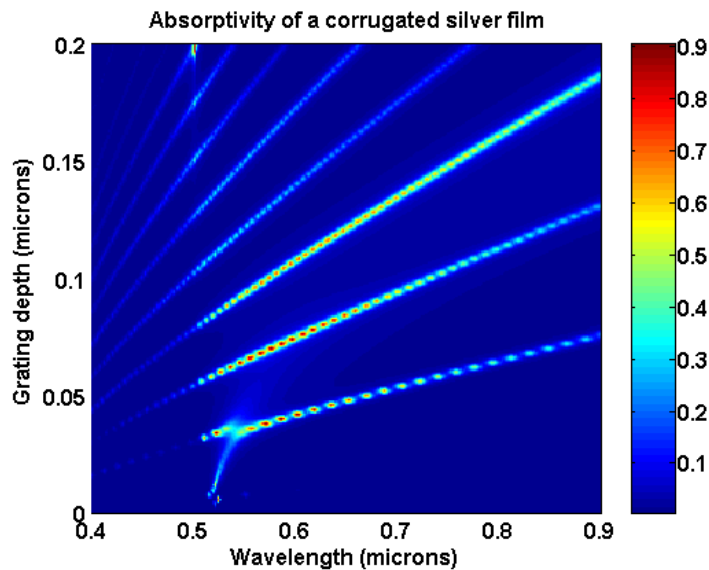
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**Rigorous Coupled Wave Analysis (RCWA):** Gives transmission, reflection, and absorption of infinite-extent gratings.

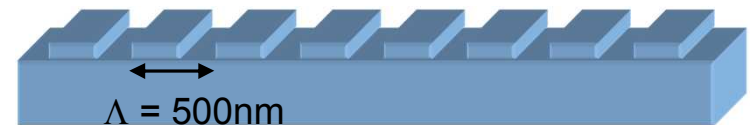
**Finite Difference Implementation of the Semi-Vectorial Helmholtz equation:** Shows near field patterns of finite-sized structures.

**Transfer Matrix Method:** Shows transmission and emission peaks.

# Absorptivity of infinite-extent metal gratings modeled with RCWA



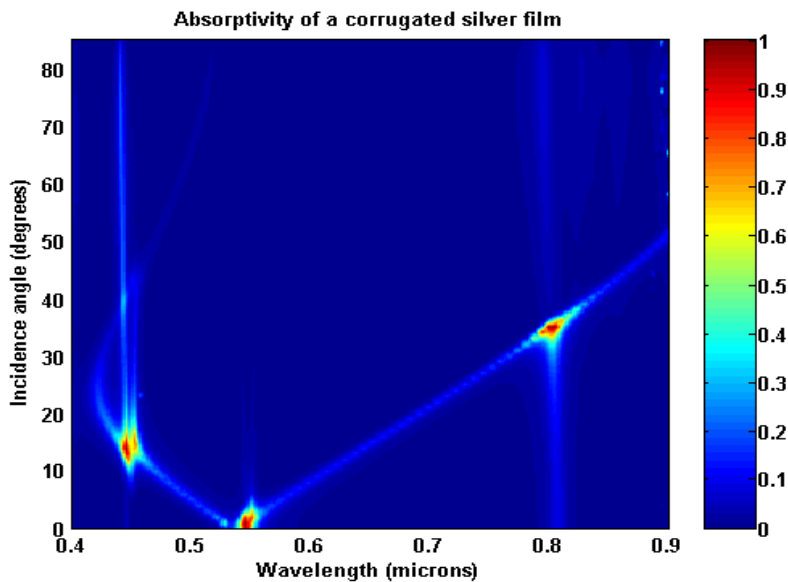
Illustrates the material issues involved in the visible portion of the spectrum.



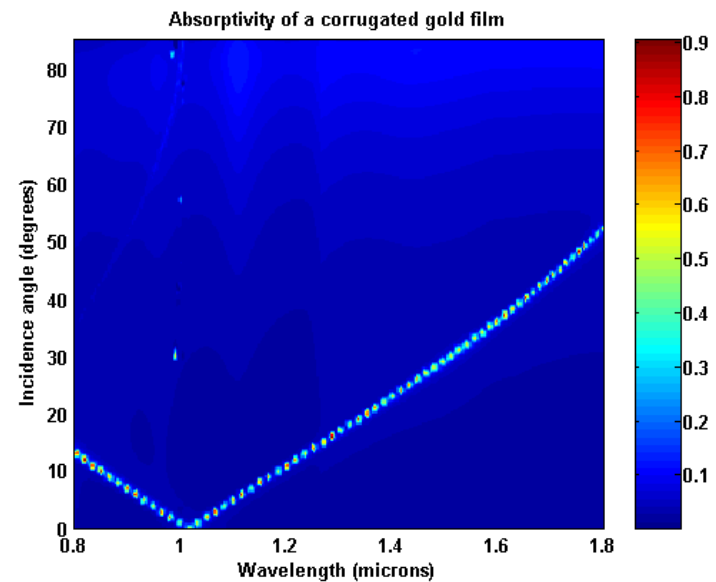


# Absorptivity as a function of angle for infinite-extent grating

RCWA results for normal TM excitation



$\Lambda = 500\text{nm}$

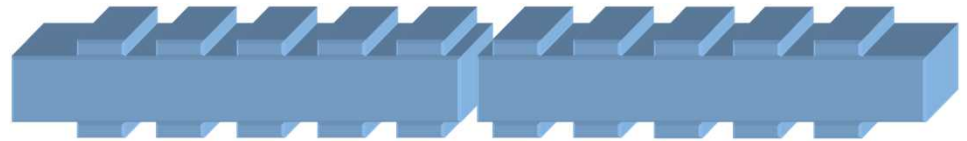


$\Lambda = 1\mu\text{m}$

RCWA modeling of single-sided gratings gives us a starting point for designing optimal structures.

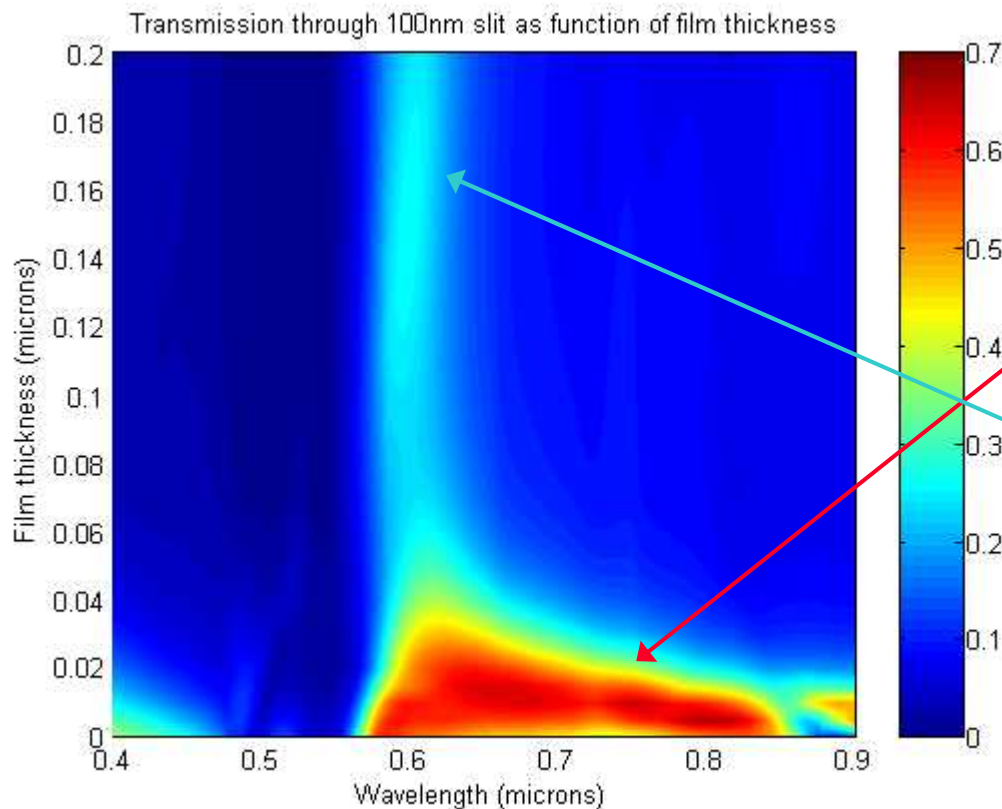
# RCWA results as function of film thickness

Metal film thickness



Front and back gratings  
have thickness of  $0.06\mu\text{m}$ .

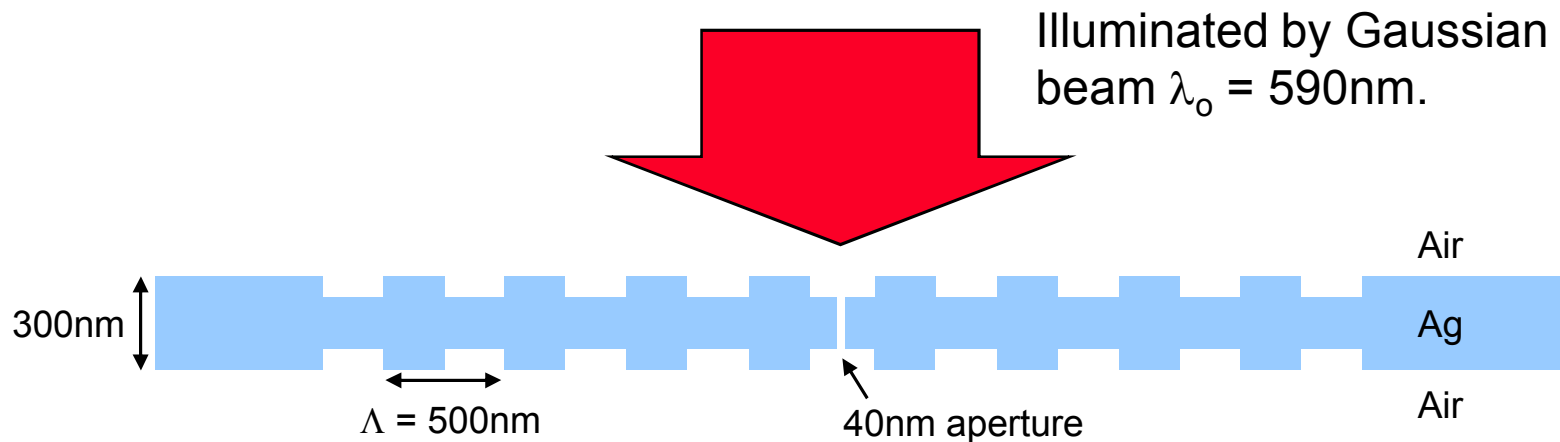
Aperture width:  $0.1\mu\text{m}$



With an extremely thin film  
layer, light couples through the  
film over many wavelengths.

As the film thickness  
increases, only the wavelength  
coupled through the aperture  
by the surface waves is  
transmitted.

# Modeling of near field with finite-difference Helmholtz equation code



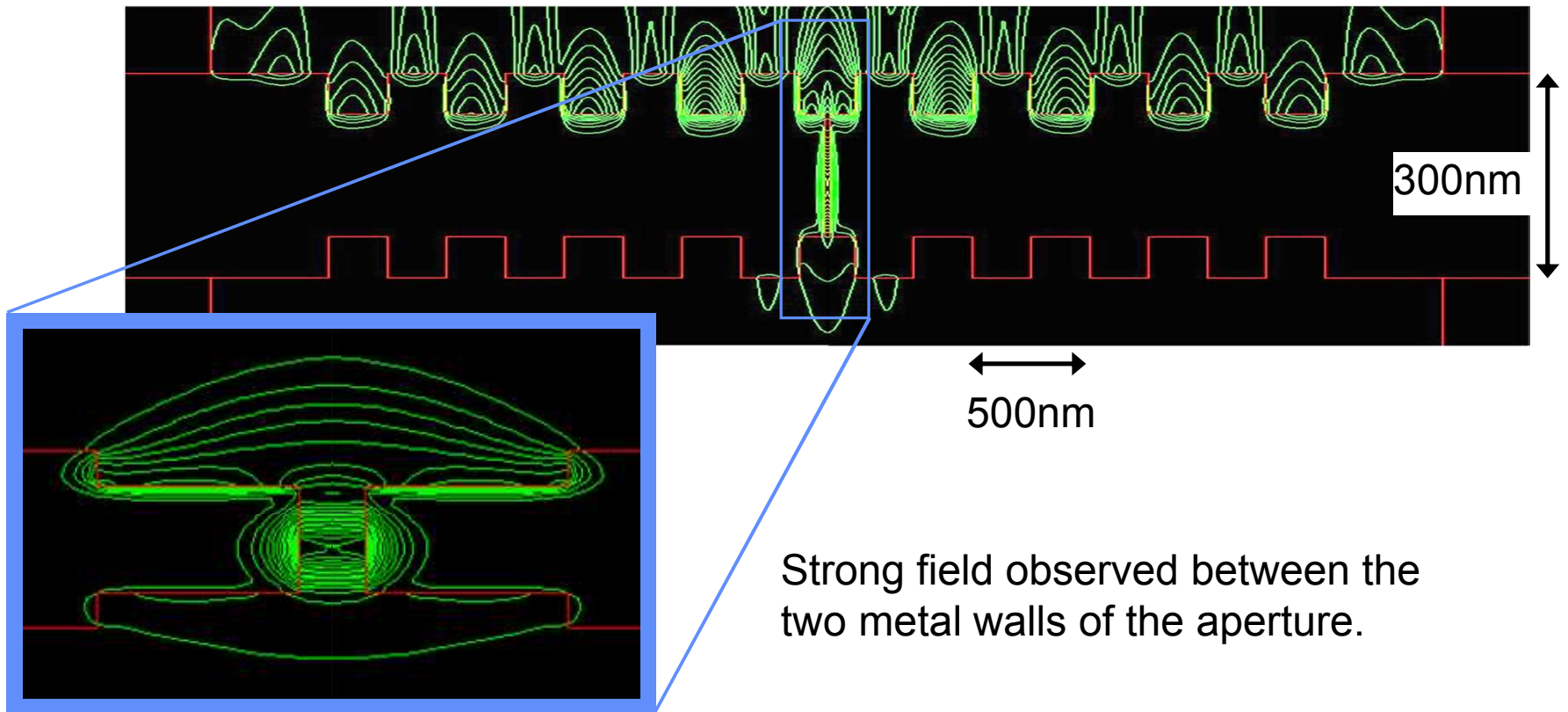
Due to rapid extinction coefficient of the evanescent surface waves, a fine discretization of spatial coordinates is required for proper results. For these results  $\Delta x = \Delta y = 5\text{nm}$ .

H. J. Lezec, A. Degiron, E. Devaux, R. A. Linke, L. Martin-Moreno, F. J. Garcia-Vidal, T. W. Ebbesen, "Beaming Light from a Subwavelength Aperture", *Science*, vol. 297, pp. 820-822, 2 Aug. 2002.

H. J. Lezec, T. Thio, "Diffracted evanescent wave model for enhanced transmission through subwavelength hole arrays," *Opt. Express*, vol. 12, p. 3629, (2004).

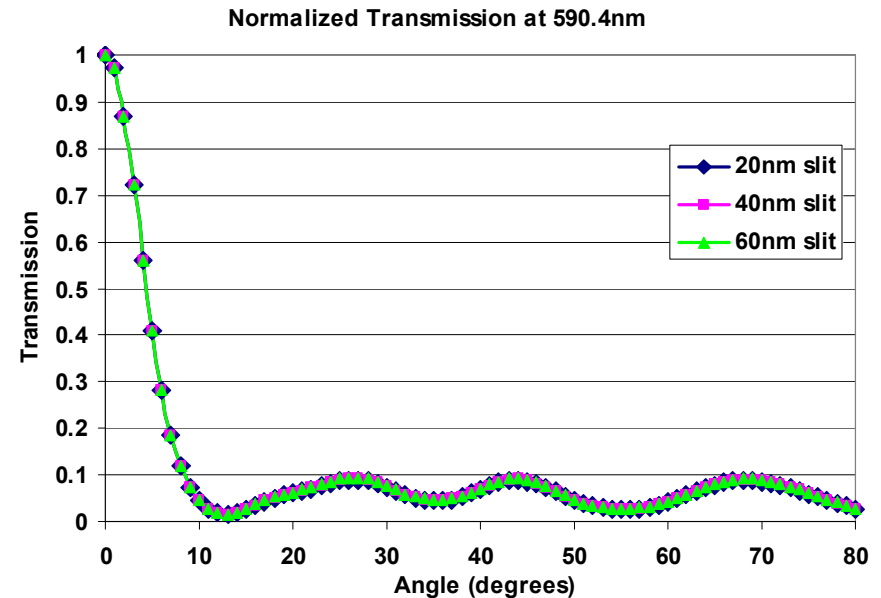
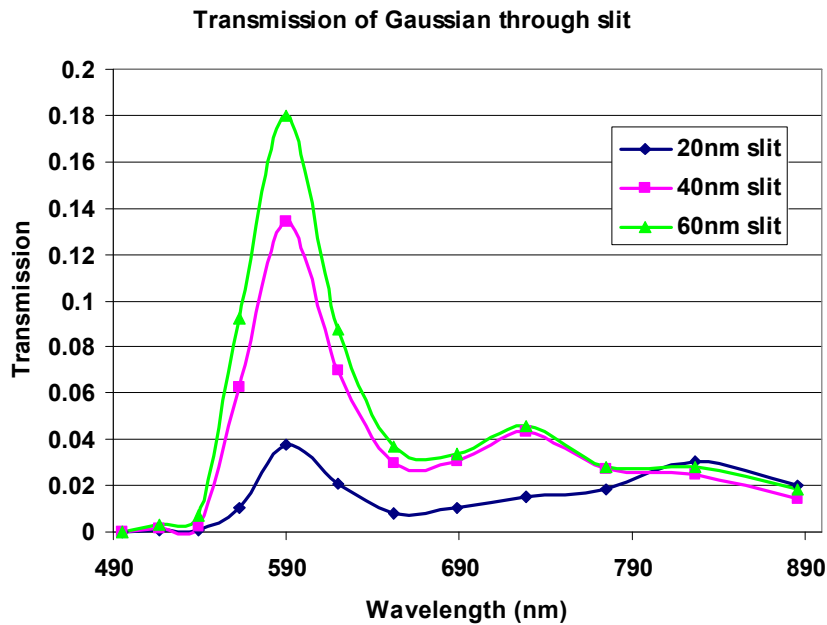
# Transmission through 40nm aperture

FDM Helmholtz code results:



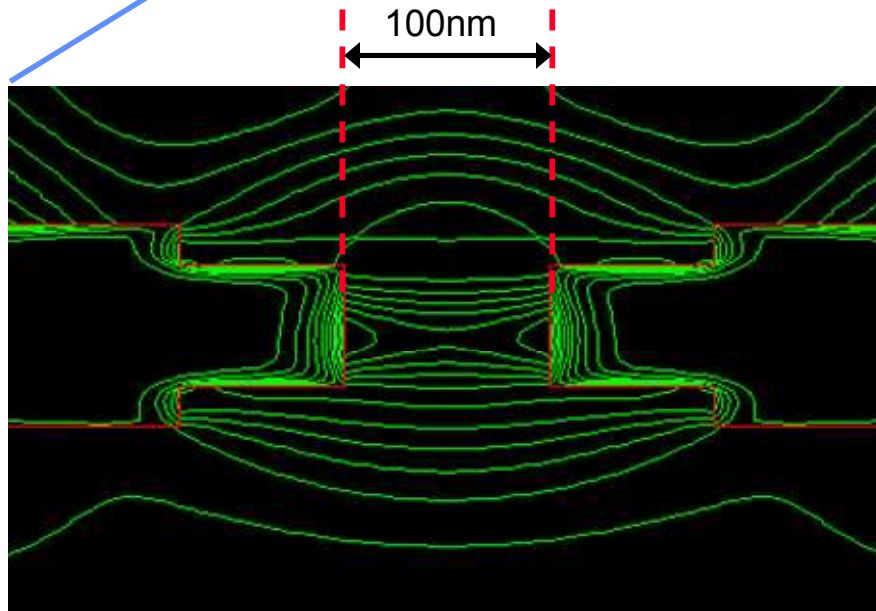
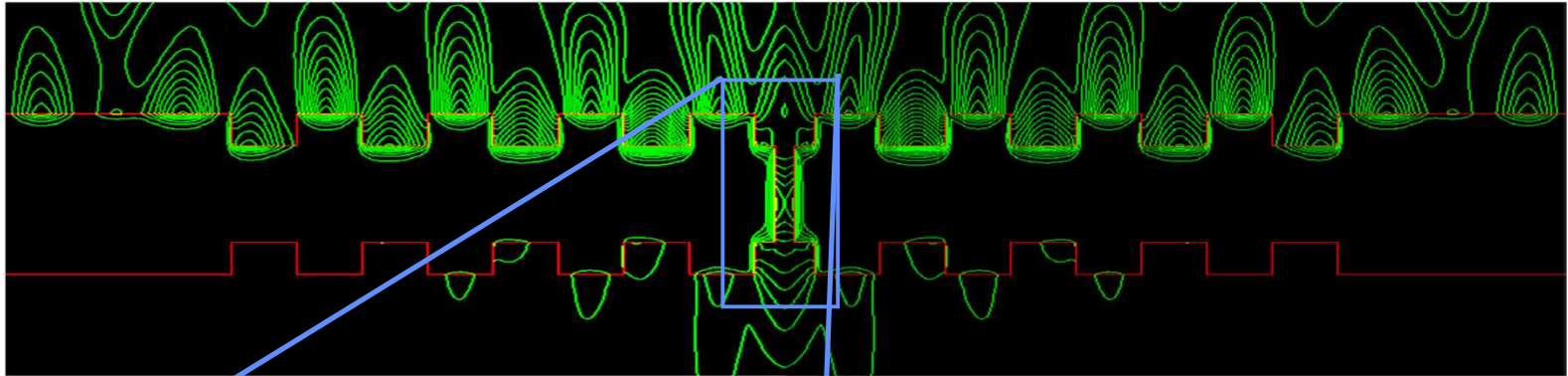


# Comparison of transmission for three slit widths



**Although the spectral response varies with aperture width, the angular divergence at 590.4nm is near identical.**

# Increase of aperture width increases transmission to a point

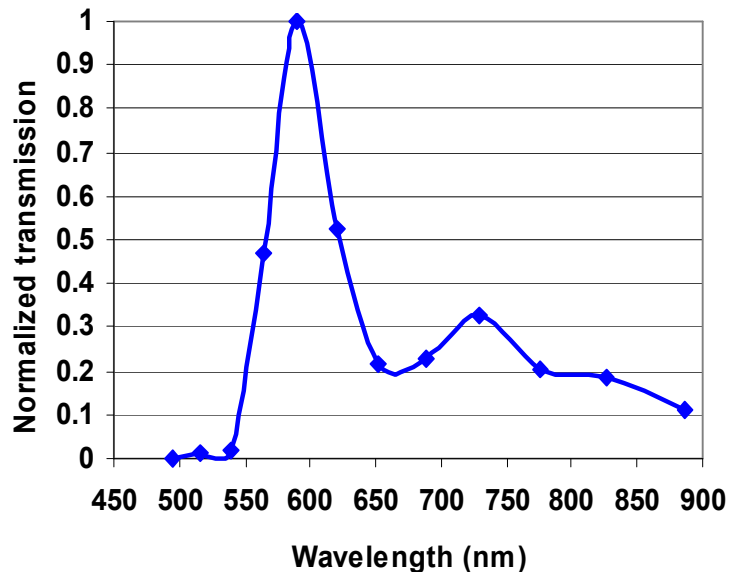


By an aperture width of 100nm, we begin to see a drop in the field that spans the aperture.

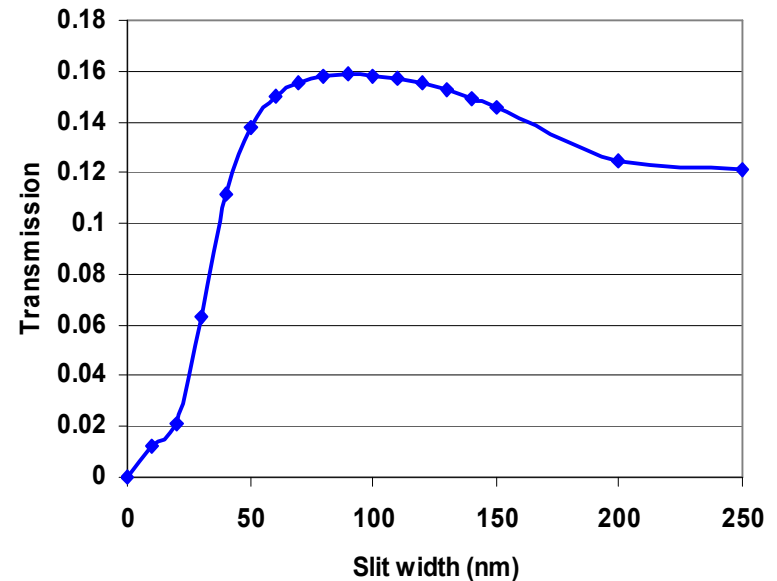
The skin depth for air/silver interface at 500nm is ~275nm.

# Optimization of aperture width

While the period can be adjusted to shift the transmission peak in the spectrum, the grating depths and aperture width can be optimized to maximize this transmission.



Normalized transmission of a 4μm-wide Gaussian through a 40nm linear aperture in silver film as a function of wavelength.

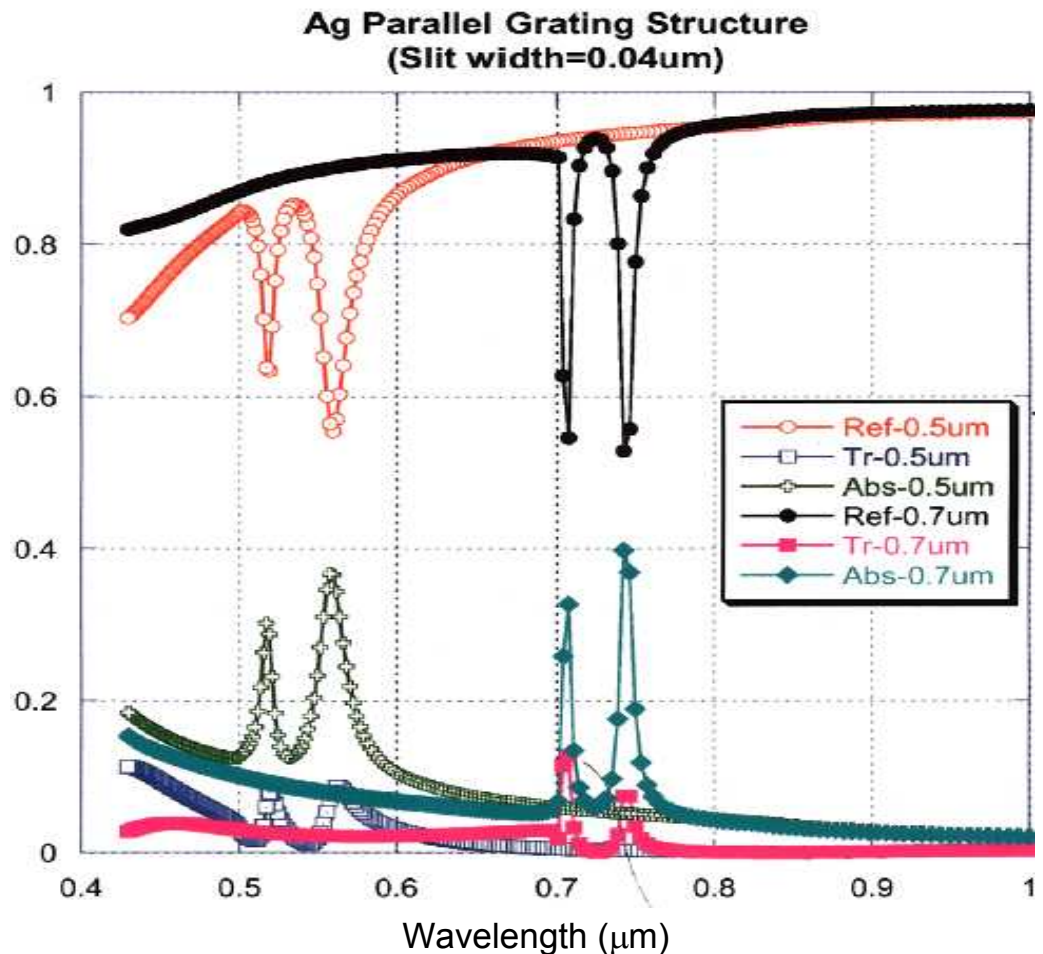


Transmission of 4μm wide Gaussian through slit in linearly-patterned silver 300nm thick film with dual-sided 60nm-deep gratings.

# Emissivity calculated using transfer matrix method

Demonstrates ability to model and design absorption peaks in real metal films.

Double peak the result of changes in discretization to decrease run time.



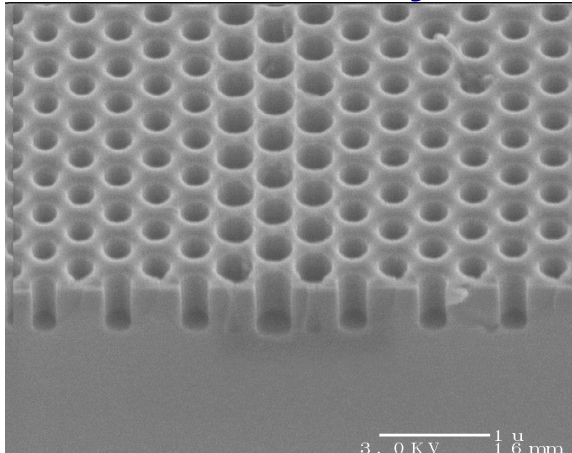


# Photonic crystal modeling and fabrication

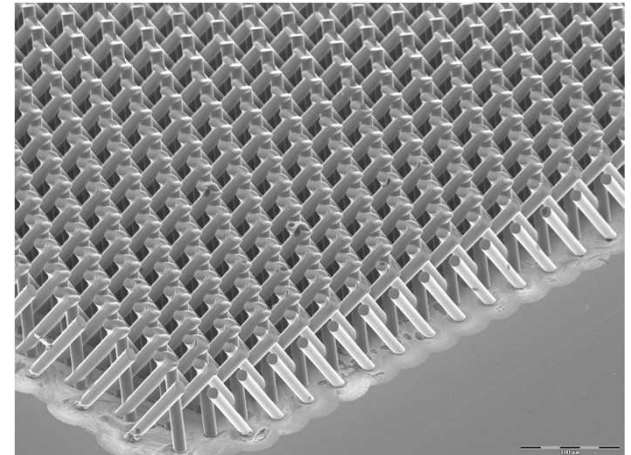
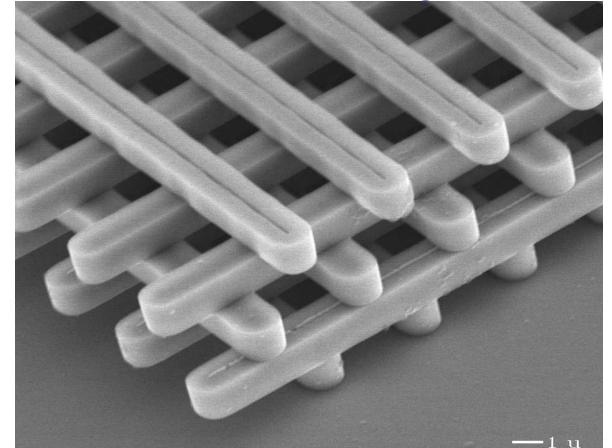
Photonic crystals have a “photonic bandgap” in the same way that semiconductors have an electronic bandgap.

The crystal structure determines the bandwidth and frequencies of the bandgap.

2D Photonic Crystal

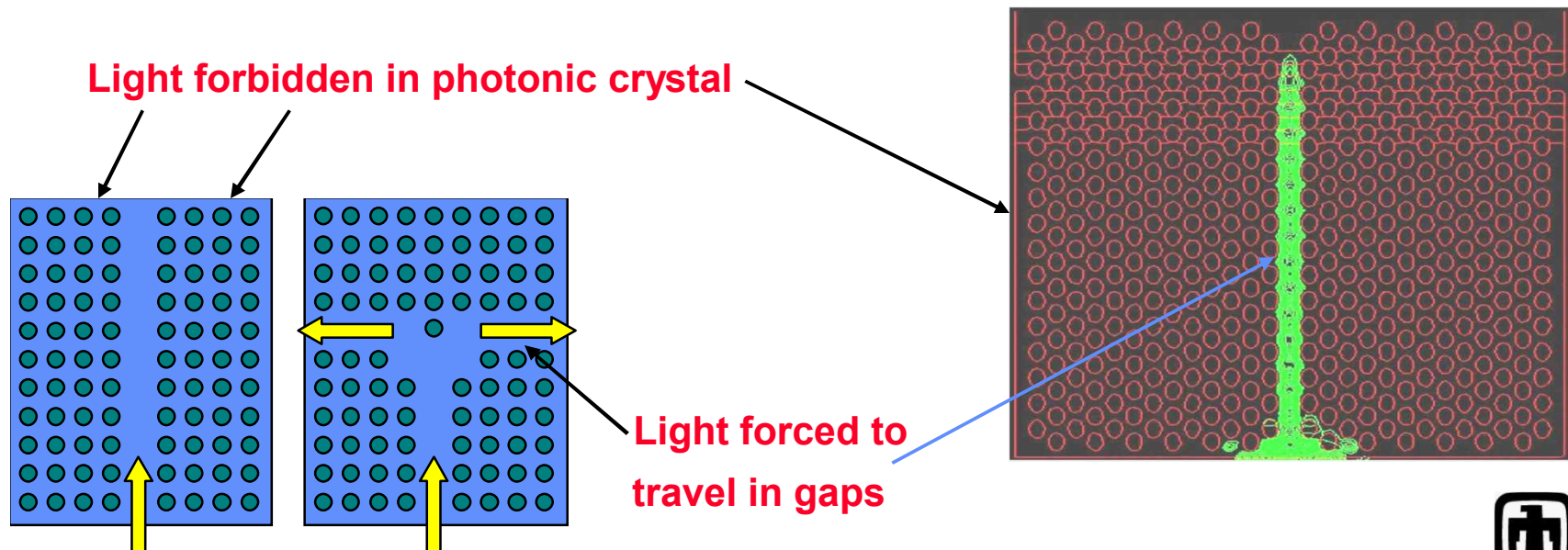


3D Photonic Crystals

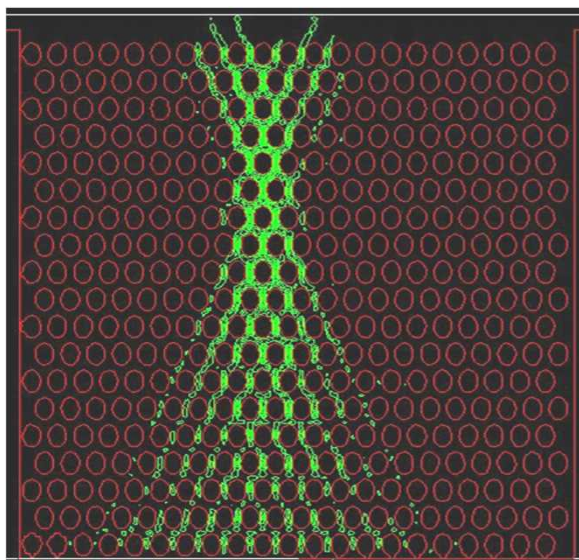


# 2D photonic crystals

- **Light is forbidden** in areas of the photonic crystal at certain wavelengths.
- We can make sharp bends
- We observe a **negative index of refraction** at some wavelengths
- We observe a “**superprism**” effect at some wavelengths: where a small incident angle change will lead to a huge change in the transmitted angle

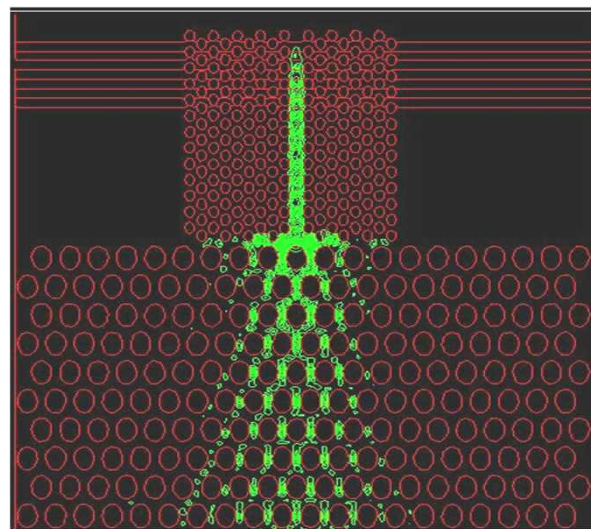


# 2D photonic crystals



Incident Gaussian diverging beam

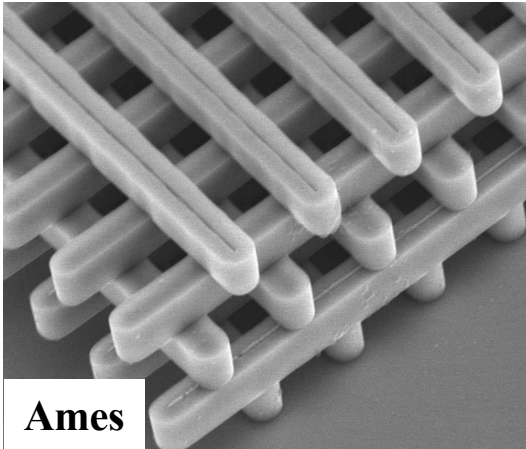
- Photonic crystal can have a **negative index of refraction**
- Causes a diverging beam to converge
- Allows us to **couple** a beam into a photonic crystal waveguide



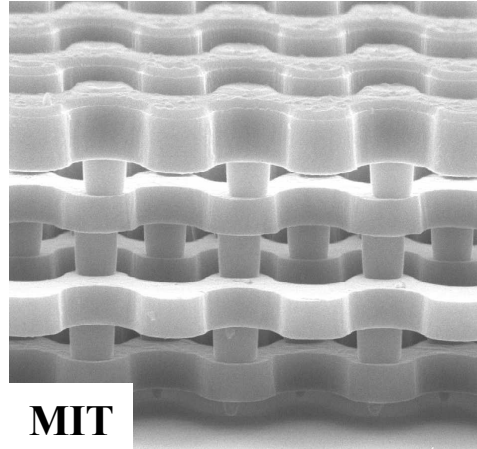
**Downside of 2D photonic crystals is a large out-of-plane losses.**



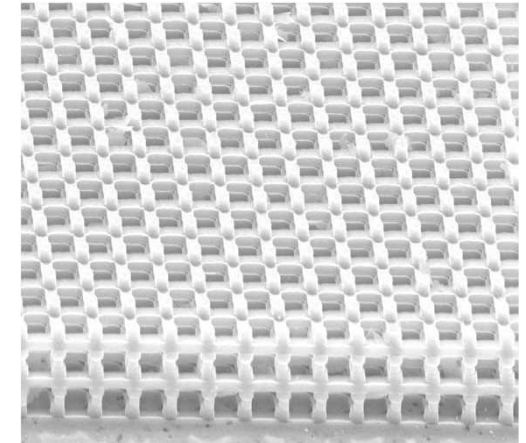
# 3D photonic crystals using Sandia's silicon advanced processing



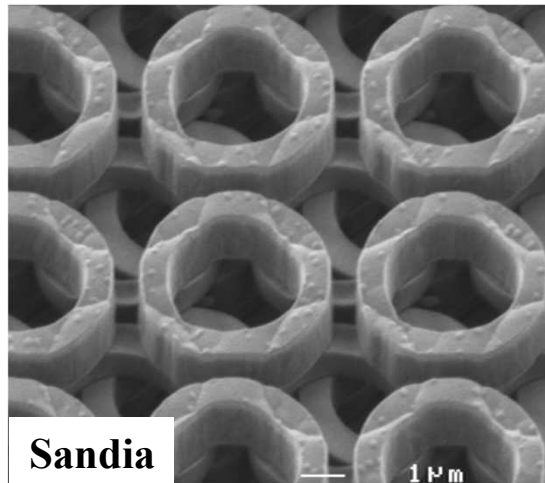
**Diamond**



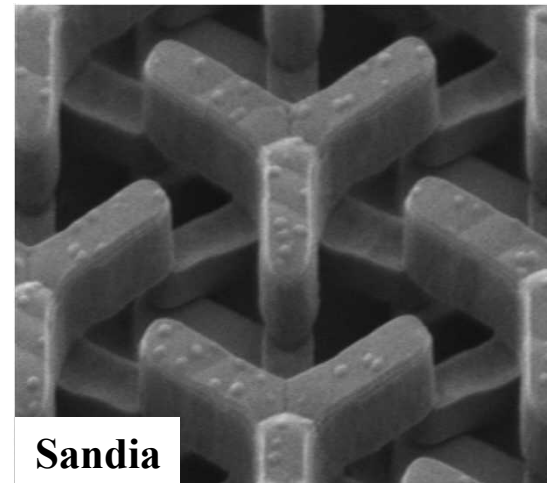
**Diamond**



**Simple Cubic**



**FCC**

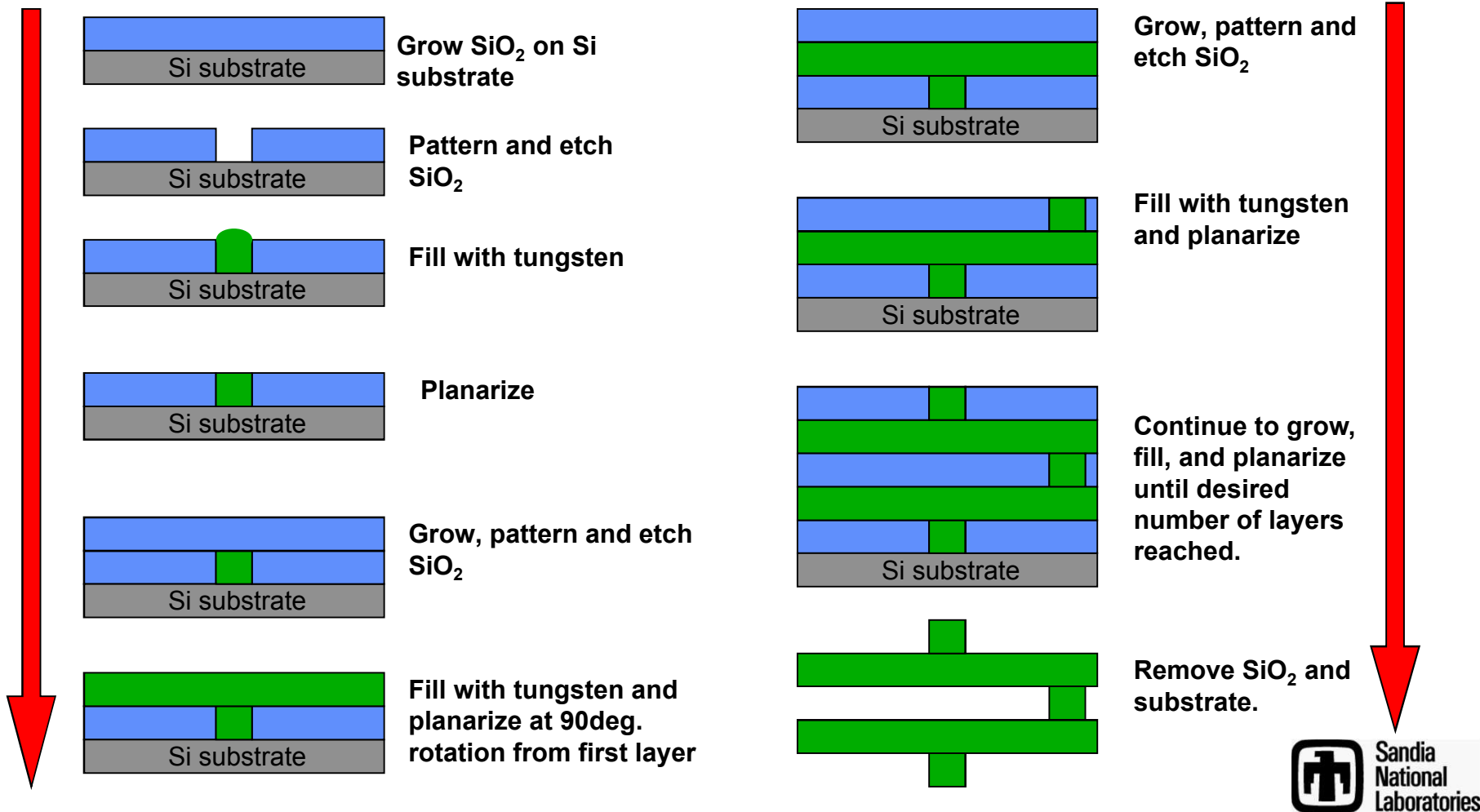


**FCC**



# Logpile fabrication steps

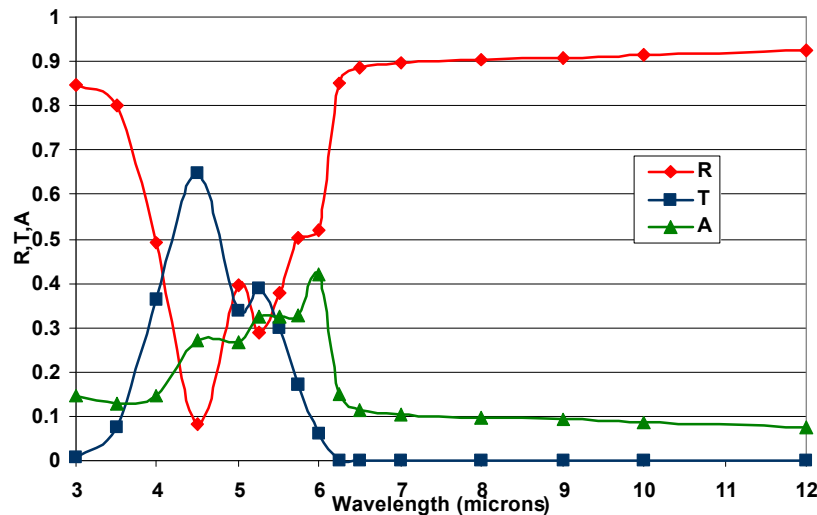
Modern lithography allows optical-frequency photonic crystals.



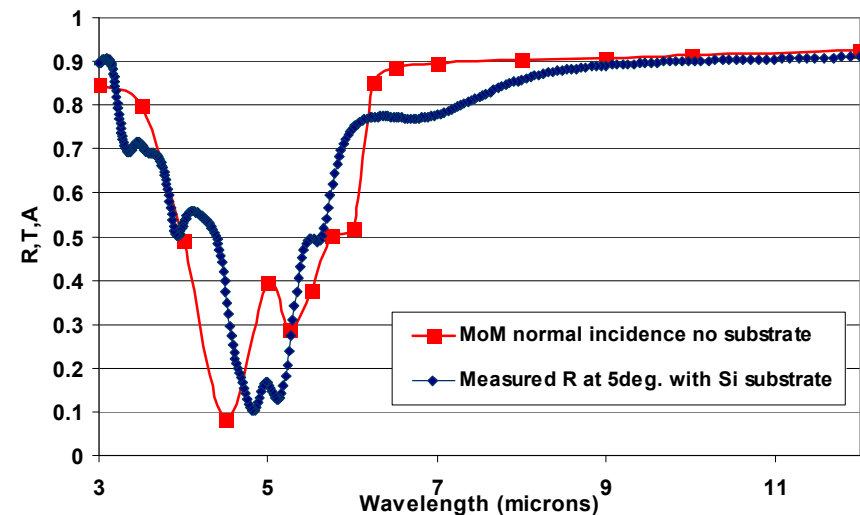
# Method-of-moments results for finite conductivity metal

For 8-layer logpile sample with no substrate or fill material.  
Uses published value for tungsten conductivity.

MoM results for reflectivity, transmissivity, and calculated absorptivity



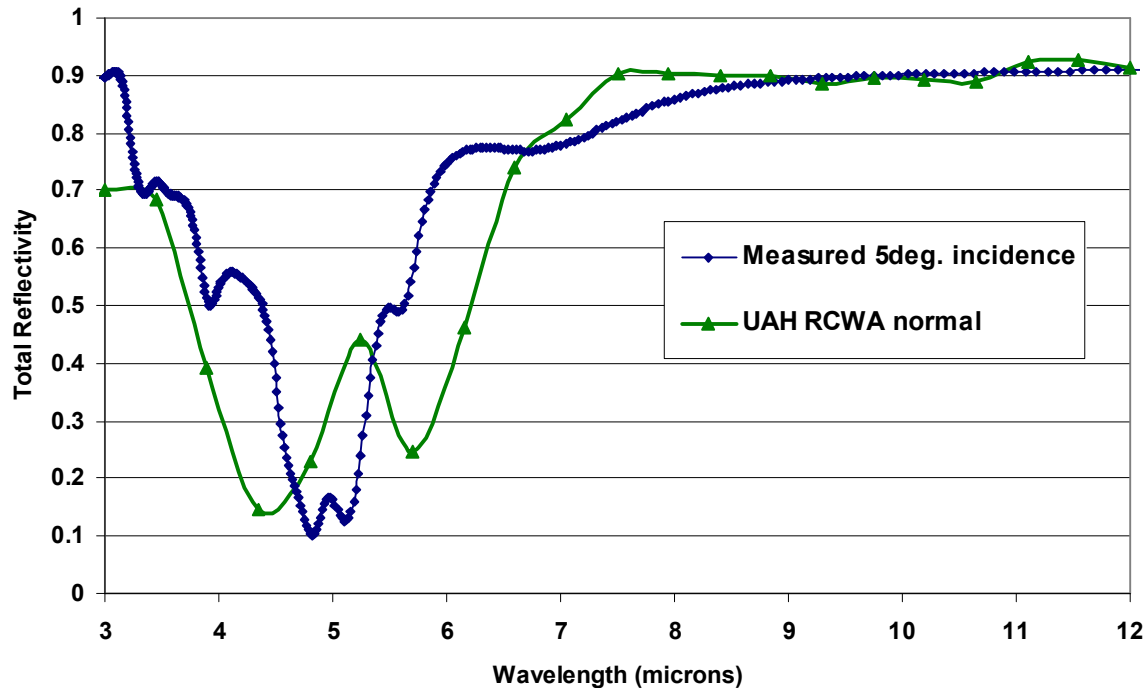
Comparison of MoM reflectivity to measured sample\*



\* MoM results are normal incidence with no substrate. Measured results are 5° from normal with silicon substrate.

Conductivity of tungsten deposited is slightly lower than published conductivity for bulk tungsten.

# Comparison of measured results to UAH RCWA code





# Conclusions

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- **Sandia has numerical modeling and fabrication capabilities for a broad range of photonic applications.**
- **Modeling takes several forms, using the most applicable tool for the task.**
- **We are always searching for more powerful and efficient modeling tools.**